

Detectors for Synchrotron Radiation Experiments- Maintaining the Status Quo or an Opportunity for change.

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- History

- Present

(some examples)

- Possible Futures

short term

longer term

The History of detectors for SR science is one of under investment.

Funding usually goes in the following sequence:-

1. Source
2. Beamlines
3. Experiment
4. Detectors (maybe) (or maybe not)

This contrasts with other areas of Science:-

HEP being the most noteworthy example

but Neutron Science also invest in detector systems as a key part of the whole drive to enable efficient use of the flux provided by the source.

We are only as strong as our weakest point !

Without co-ordinated investment, led by the science, SR will lose out long term.

Note the emphasis on “science led”.

Things that have gone wrong:-

There are many cupboards with detectors in which made it to the beamline too late (if ever!).

A fundamental flaw in what was proposed (Technical, Funding or Project Methodology)

Technology push is OK if it is linked with the true people who want to do science.

Because of inherent lack of funding and large opportunities some projects are overly ambitious or so wide in their constituents that they do not deliver specifics.

Where is the SR community at the present with detectors?

In the 1990's at the very latest!

SRI 91 Prof. Mike Hart's keynote speech pointed out the widening gap between source provision and detector capability.

Has the situation changed since then?

In a small number of cases yes!

In a number of cases some key progress has been made.

(but availability to the wider community?)

In a large number of cases no (or slow) progress because of lack of critical mass.

Or it has got worse?

Successful conventional approaches to development:-

Incremental, longer term.

Usually drip feed of small amounts of funding over several projects.

Extension of science area slow and can lead to FBAD (funding body attention deficit).

Successful More Radical approaches to development:-

Step change development, short term.

Borrow what you need to prove things work, limit risk.

Then ask for real amounts of funding to complete, possibility of success binary. But usually gets attention.

Two examples

an incremental development which is not quite there yet

a rapid step-change development which is now available to the community.

**These are C-TRAIN X-SPRESS
and XSTRIP**

C-TRAIN X-SPRESS project

Canberra multielement 1988

prototype digital signal processor early 1992

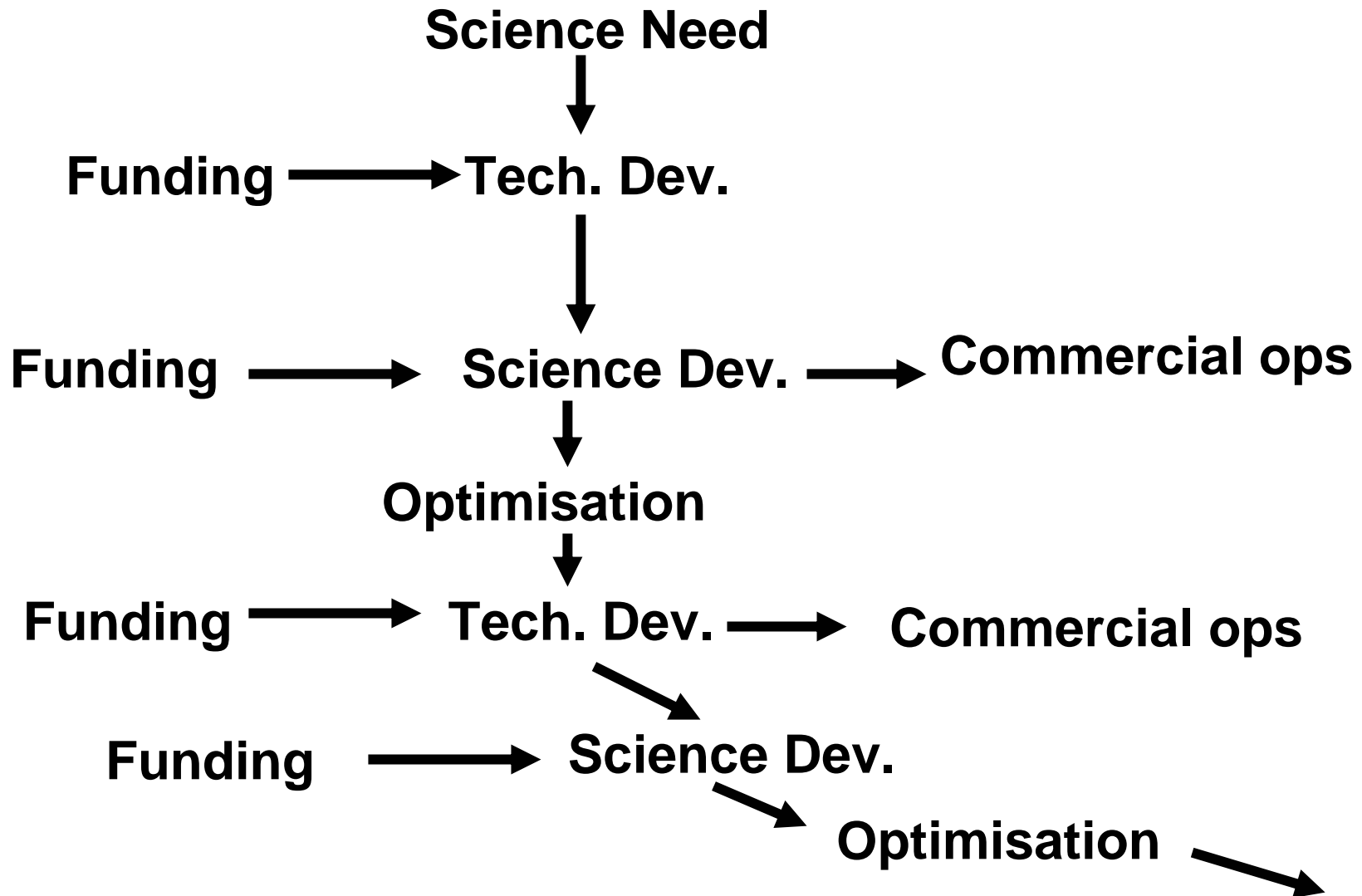
X-SPRESS system built and tested 1995

Ortec 30 element Ge plus X-SPRESS 1997

Ortec 9 element monolithic plus X-SPRESS 1998

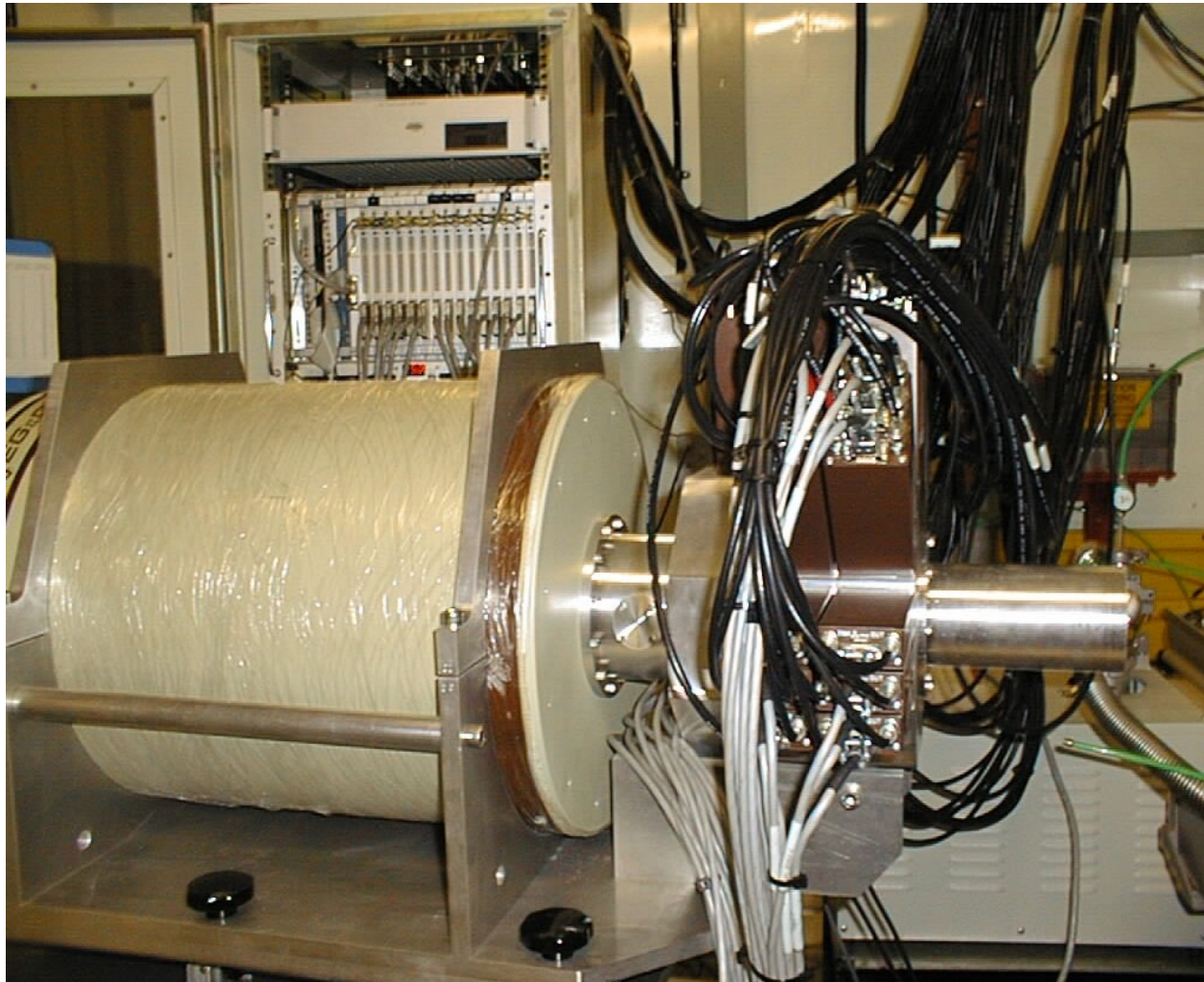
other Ortec monolithics plus X-SPRESS 2002, 2003

X-SPRESS2 2004?



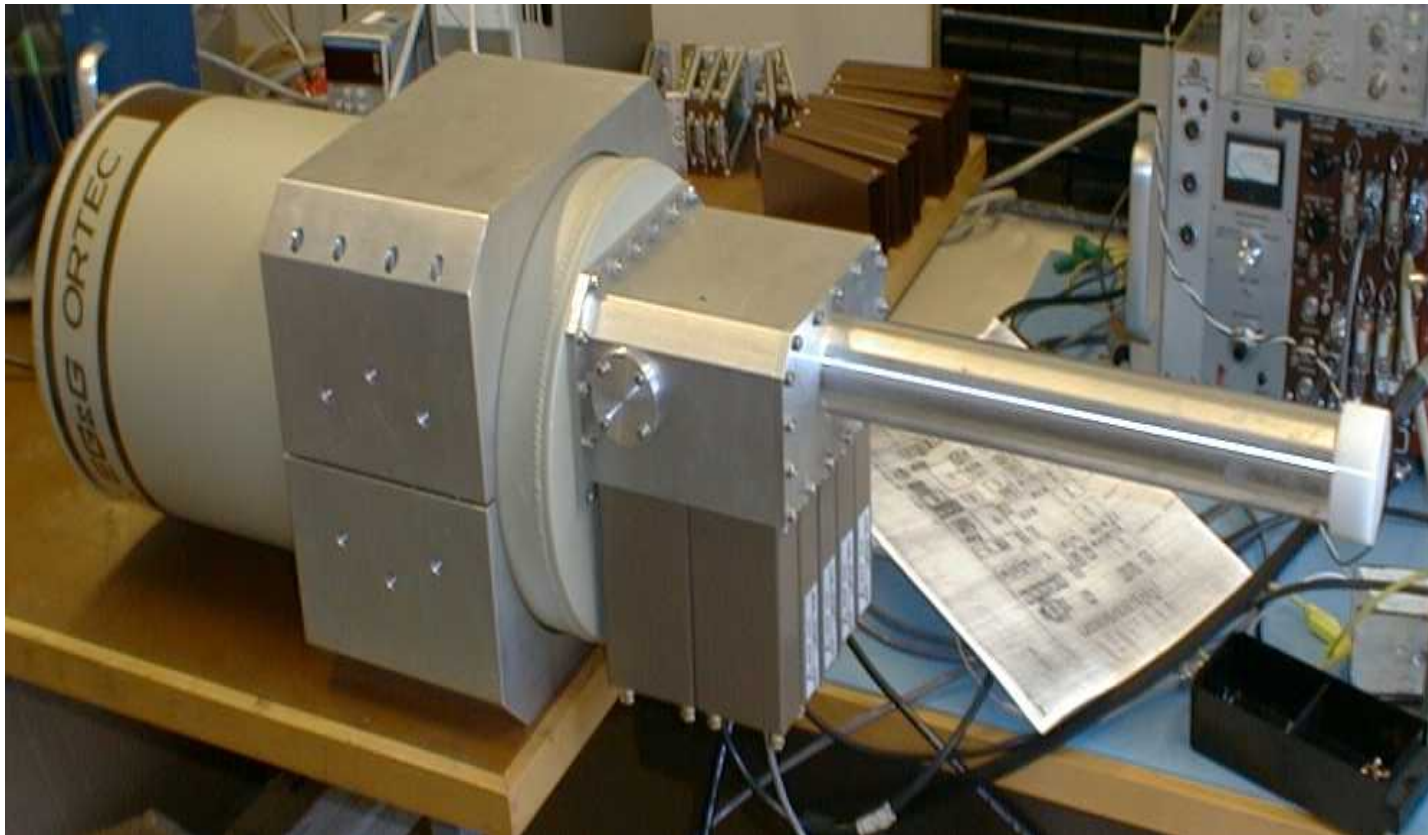
**The aim of the C-TRAIN X-SPRESS programme:-
To develop an optimised fluorescence XAS system.**

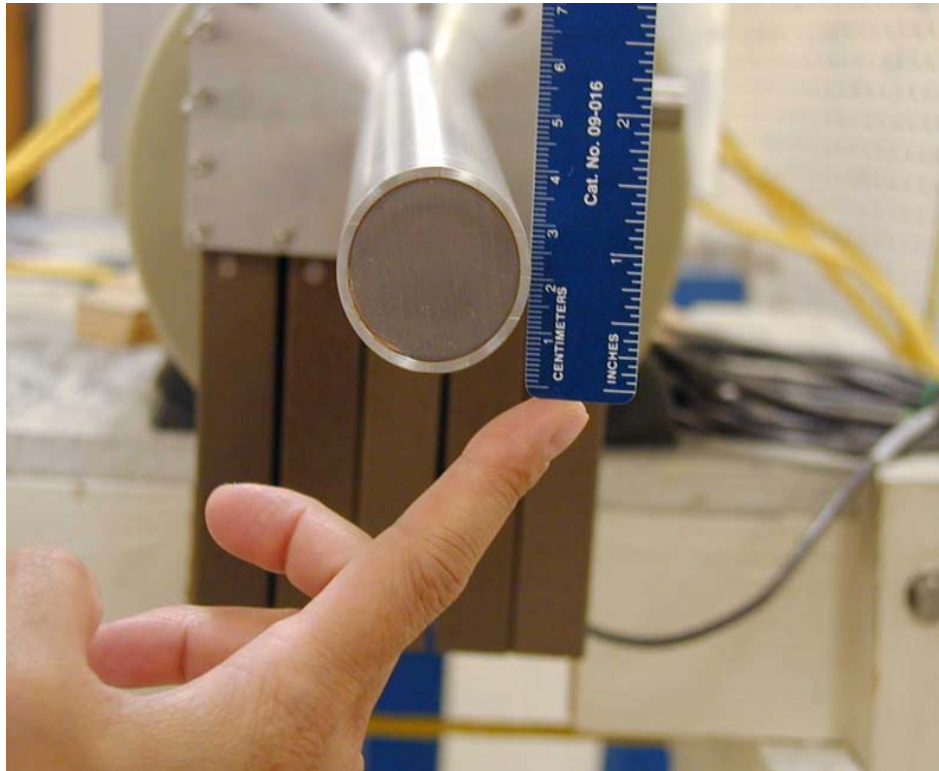
- **High throughput**
- **Flexible**
- **Compact**
- **Easy to use / low maintenance**



CTRAIN

Compact Time Resolved -XAFS Array INnovation





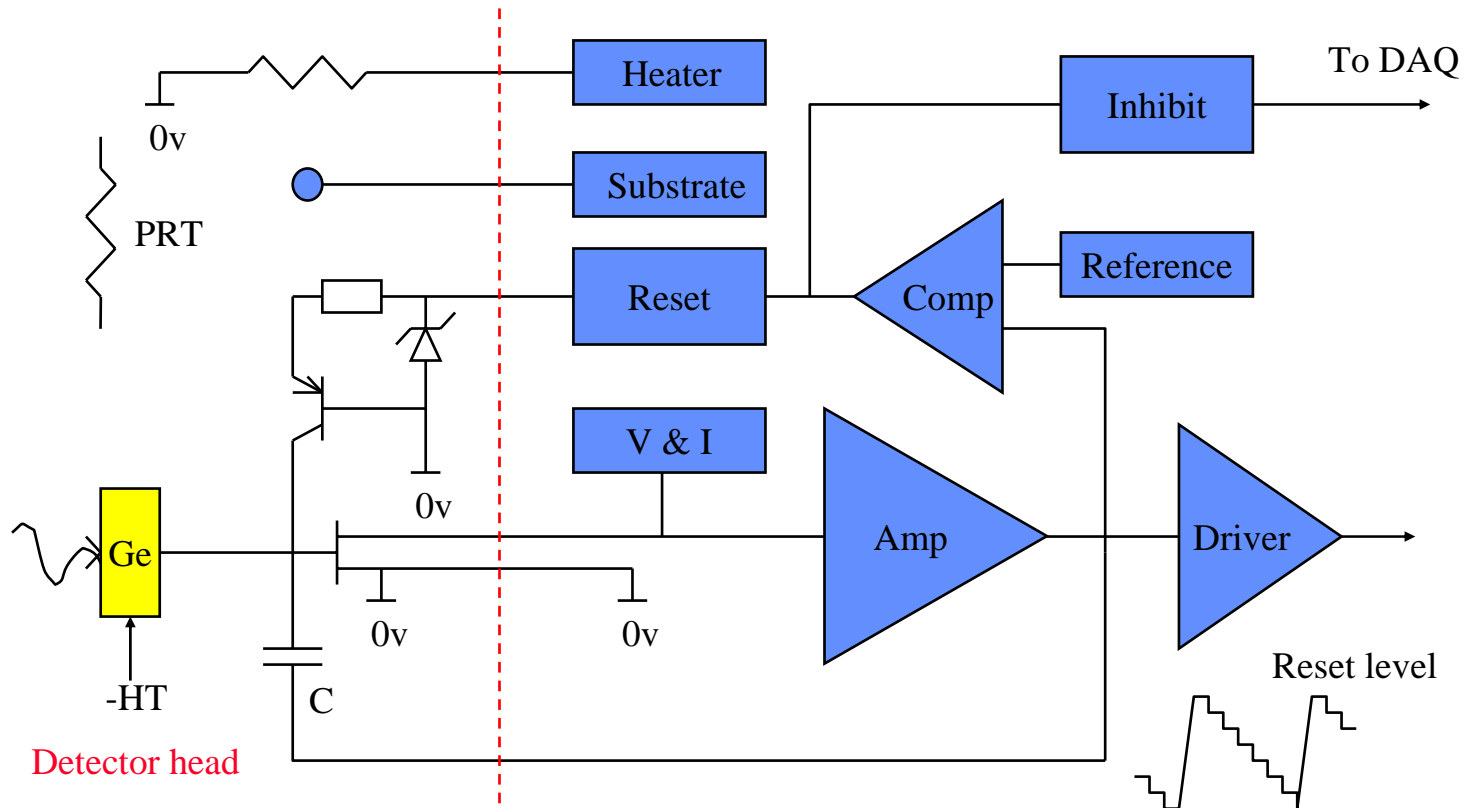
Courtesy of Pat Sangsingkeow, Ortec

The overall initial results achieved:-

- **9 Element Germanium Crystal**
- **Maximum count rate is 550k CPS per channel**

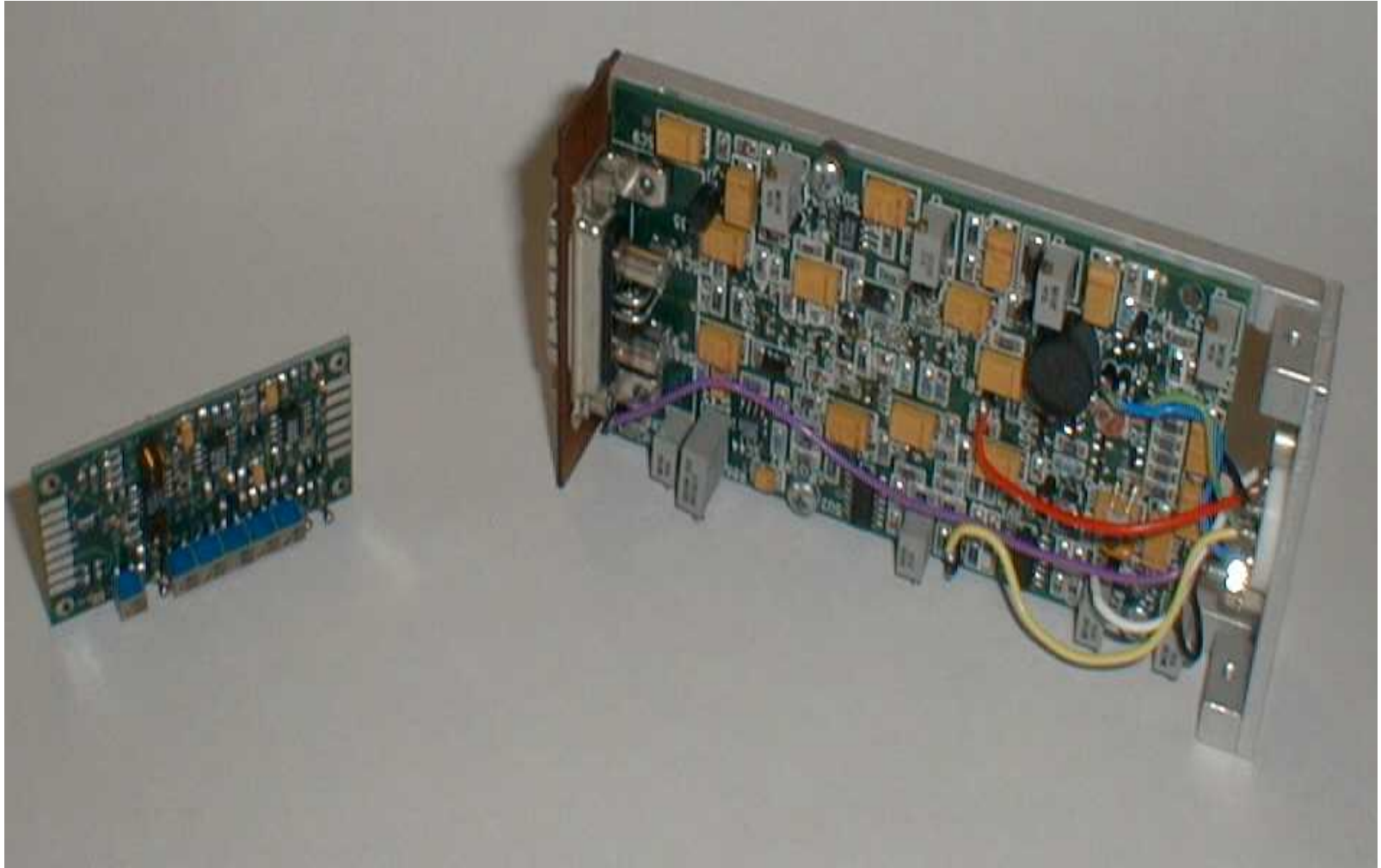
This could be improved

- **Resolution is < 200 eV FWHM, typical 170eV FWHM @ 0.5 microseconds shaping equivalent.**



- **Improve Reset Time**
- **Interface with existing DAQ and cables**
- **Retain existing good resolution**
- **Improve count rate**

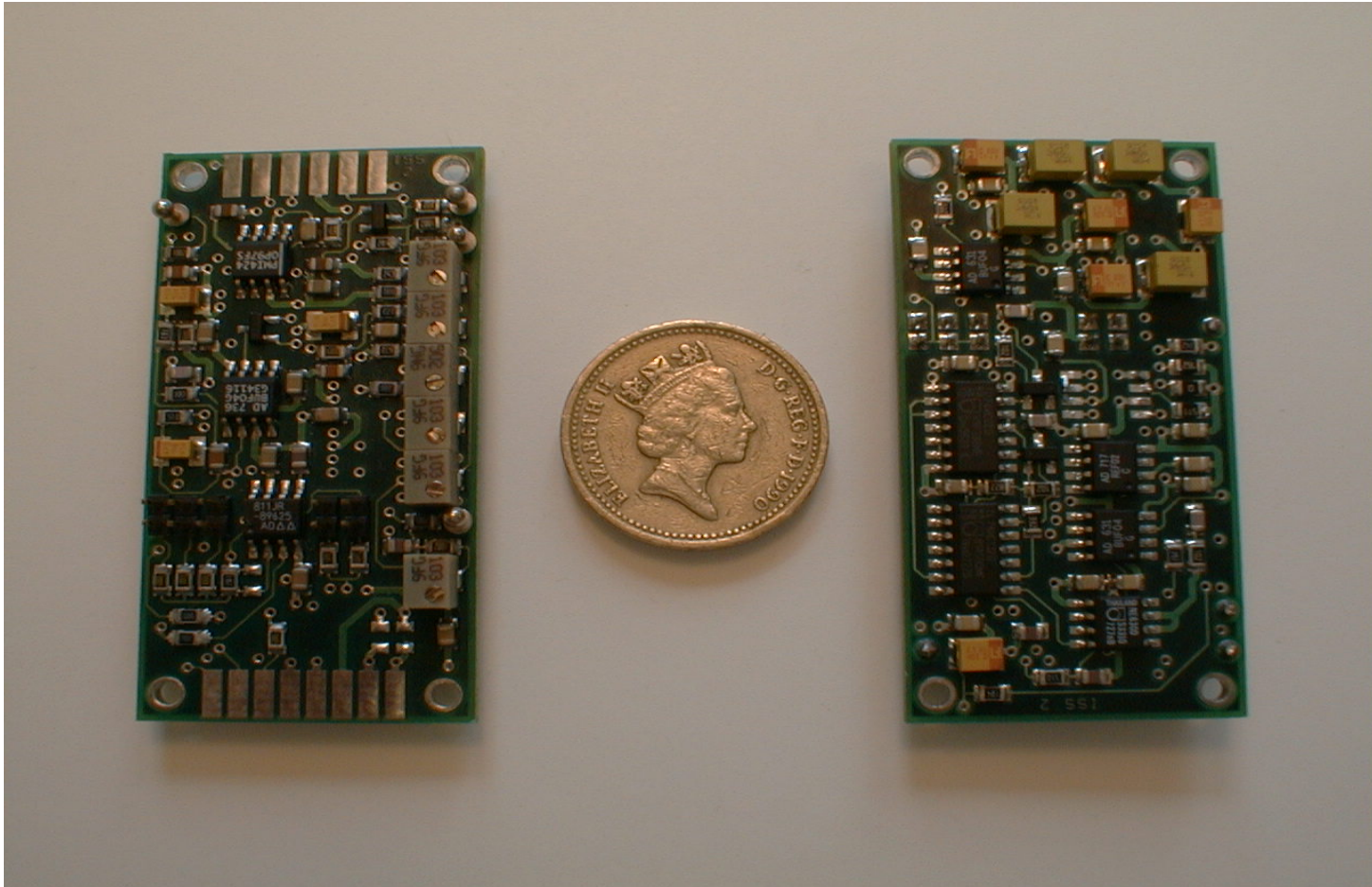
New Preamplifier compared with Previous preamplifier



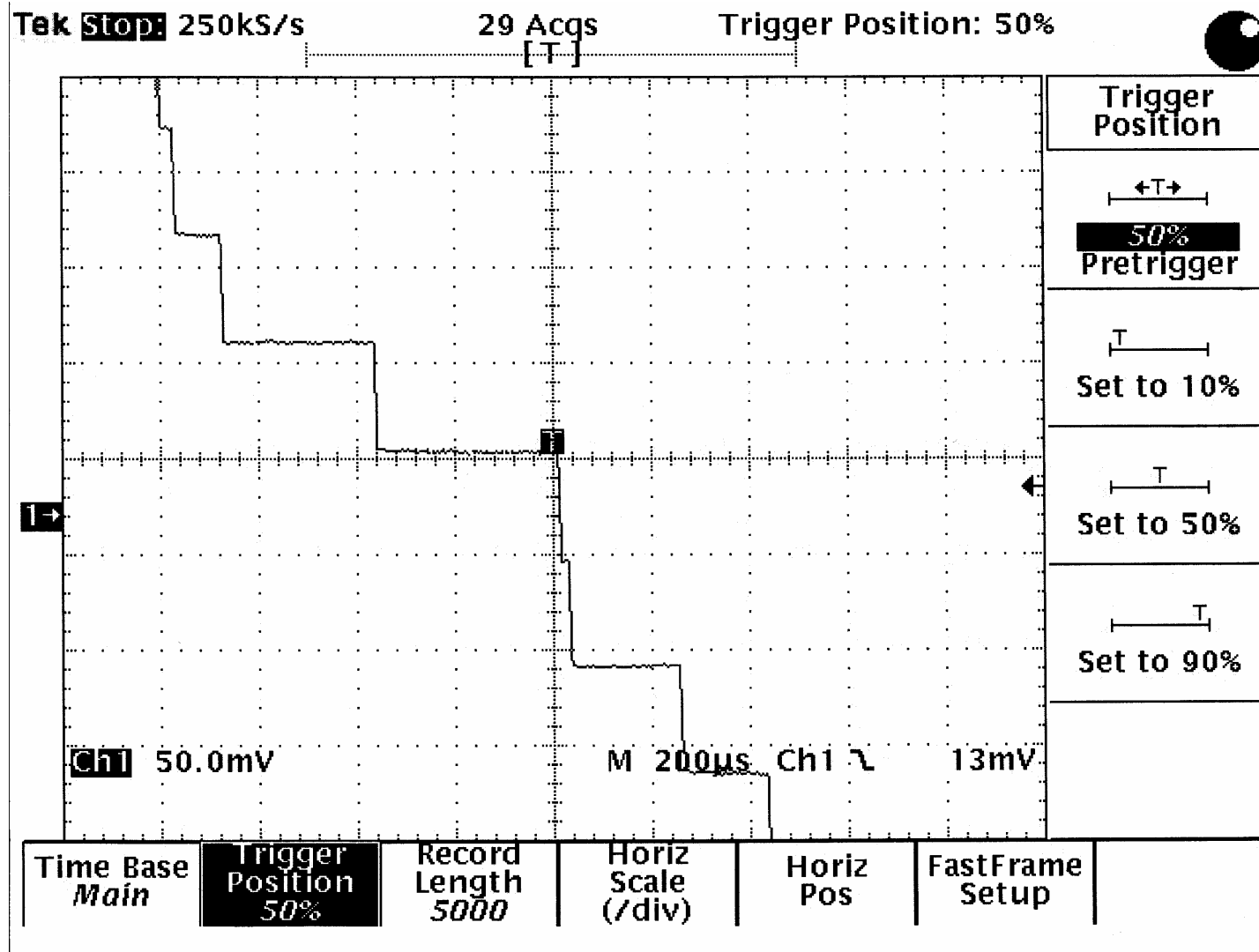
New Preamplifier

Analogue Side

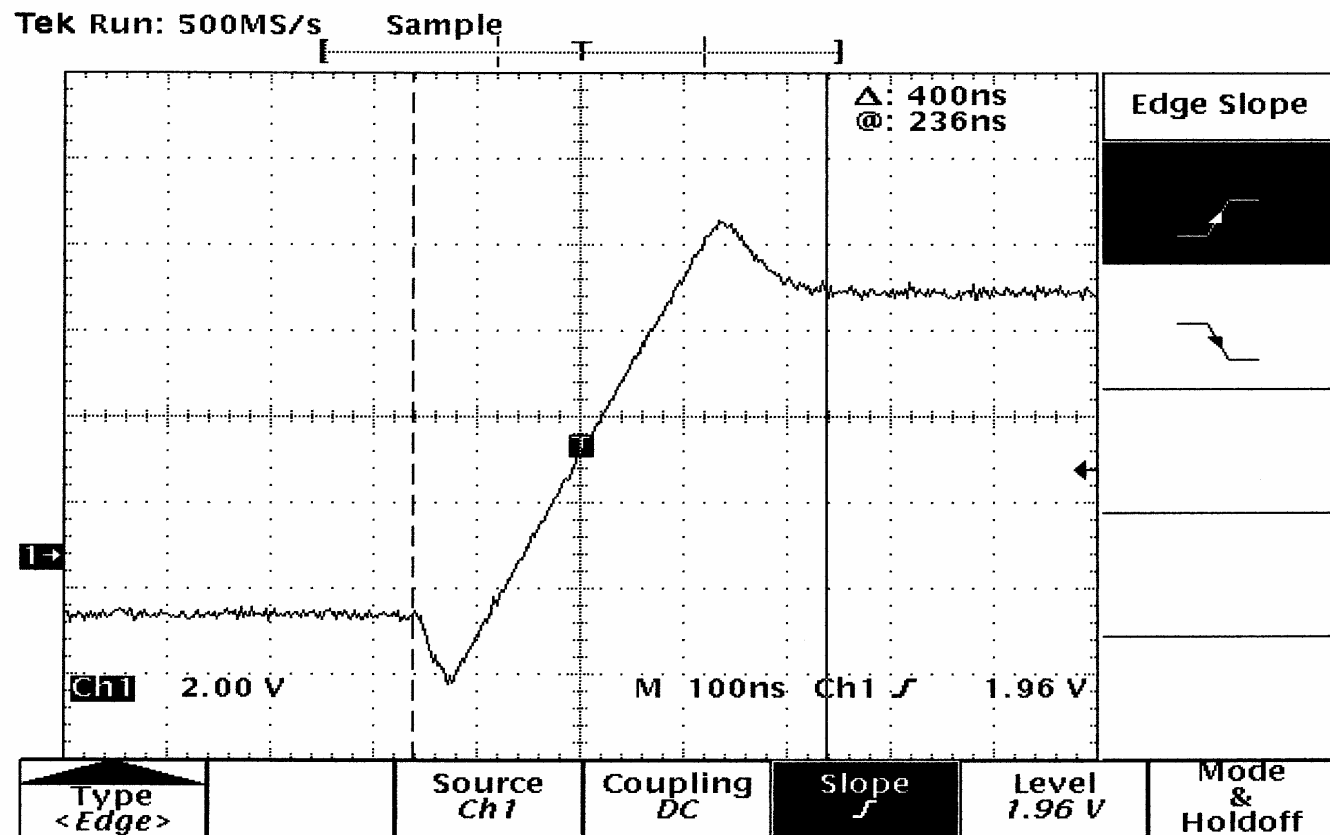
Digital Side



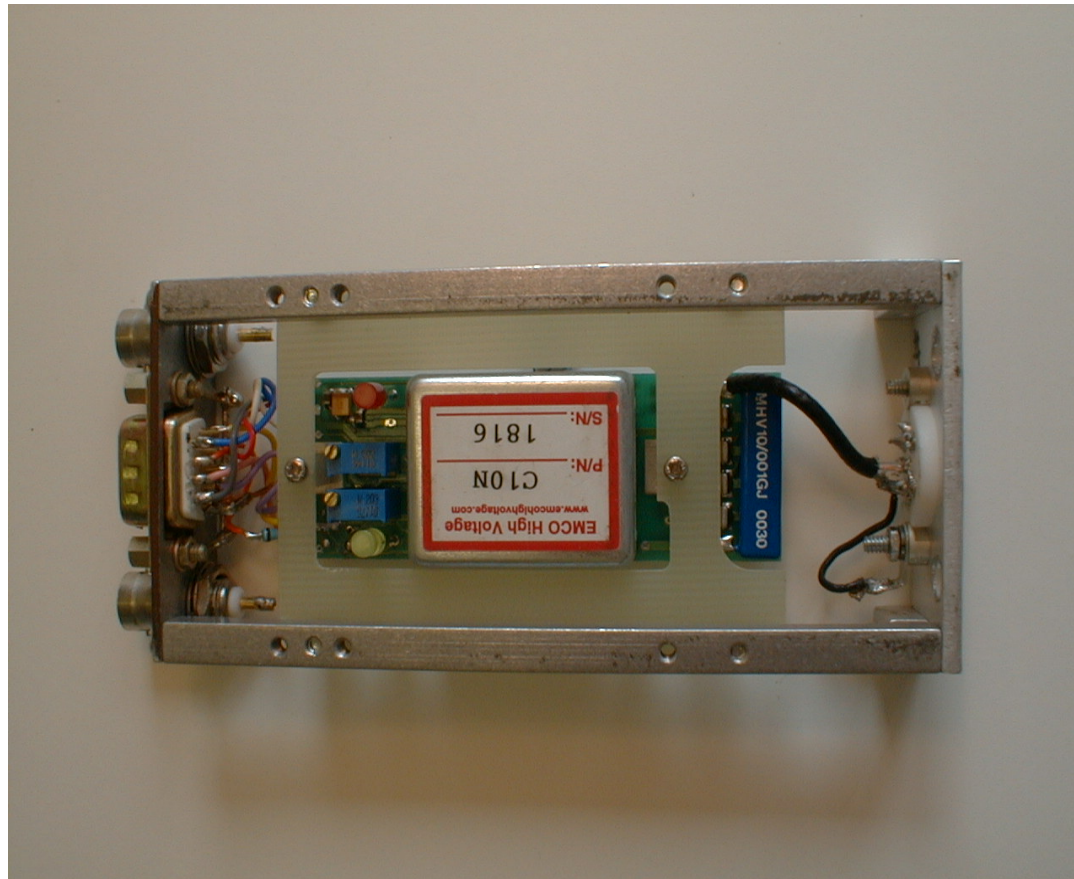
The Preamplifier Output



The C-TRAIN Preamplifier Reset

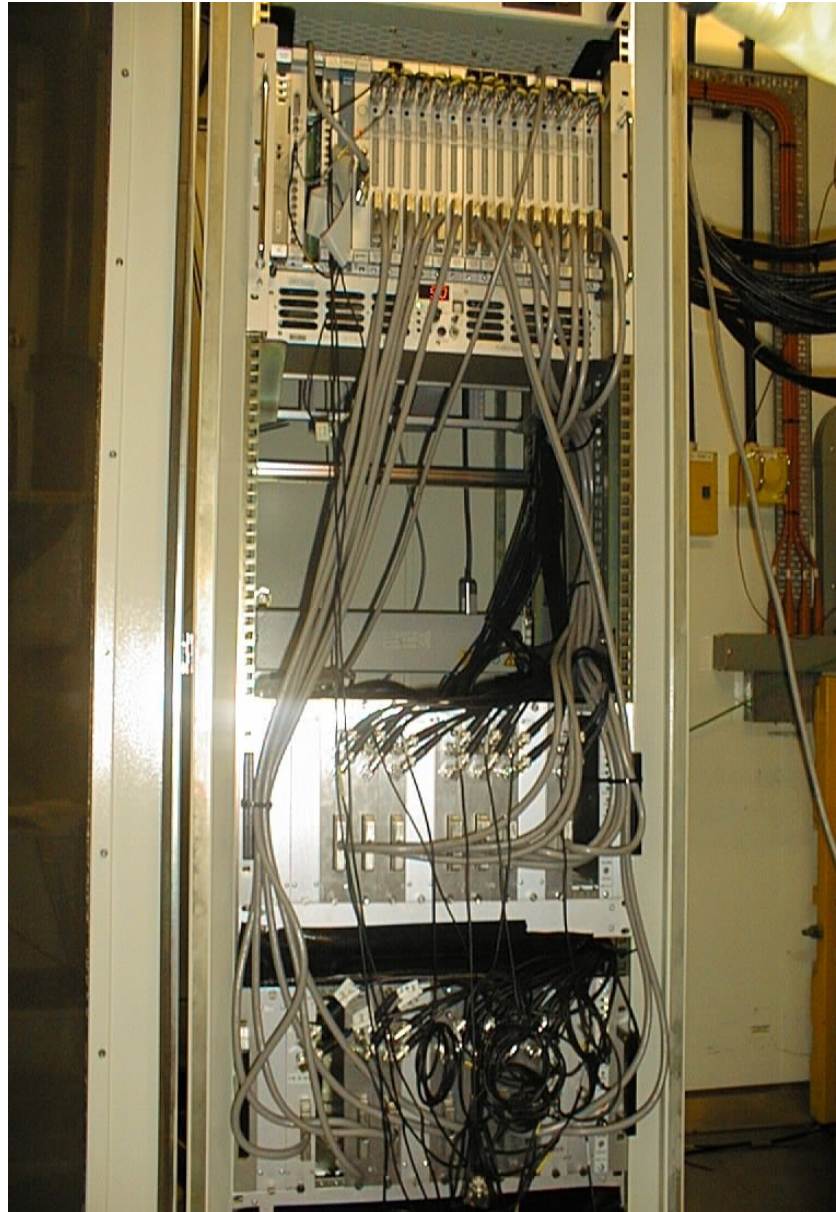


New Compact High Voltage Supply

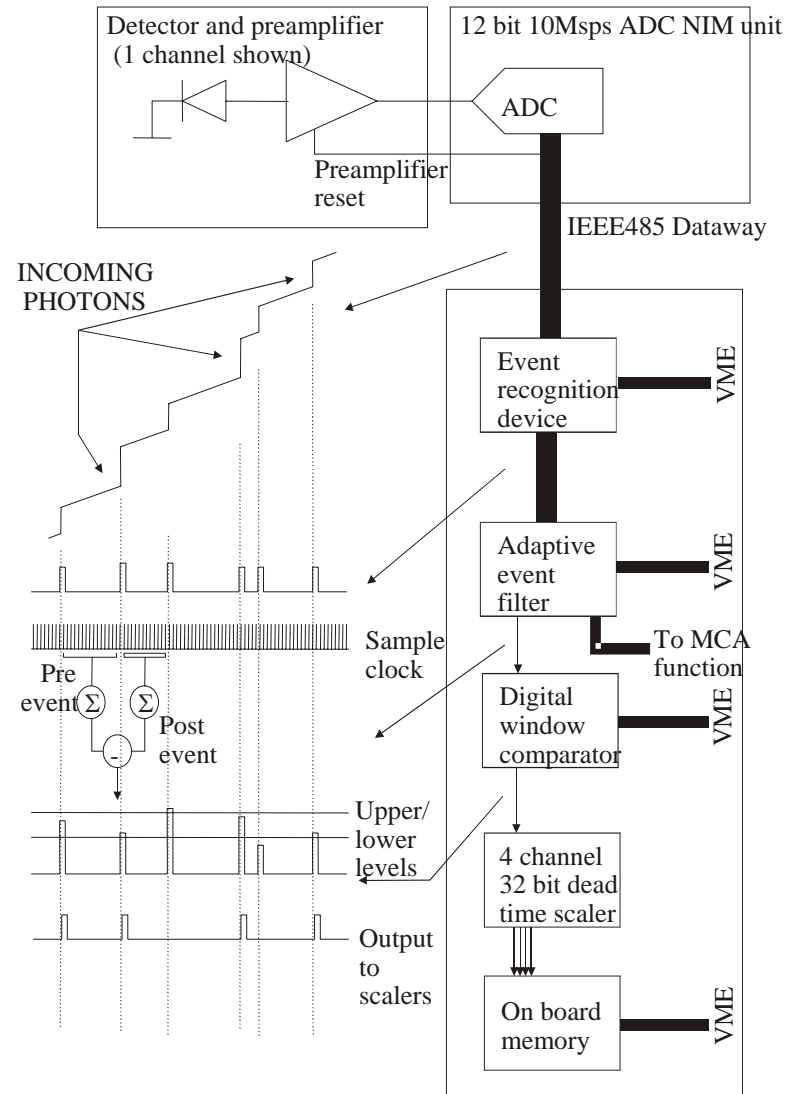


Apart from the detailed work associated with the detector and front-end....
integration into an X-SPRESS based DAQ system was relatively straightforward
due to the flexibility built into the X-SPRESS system.

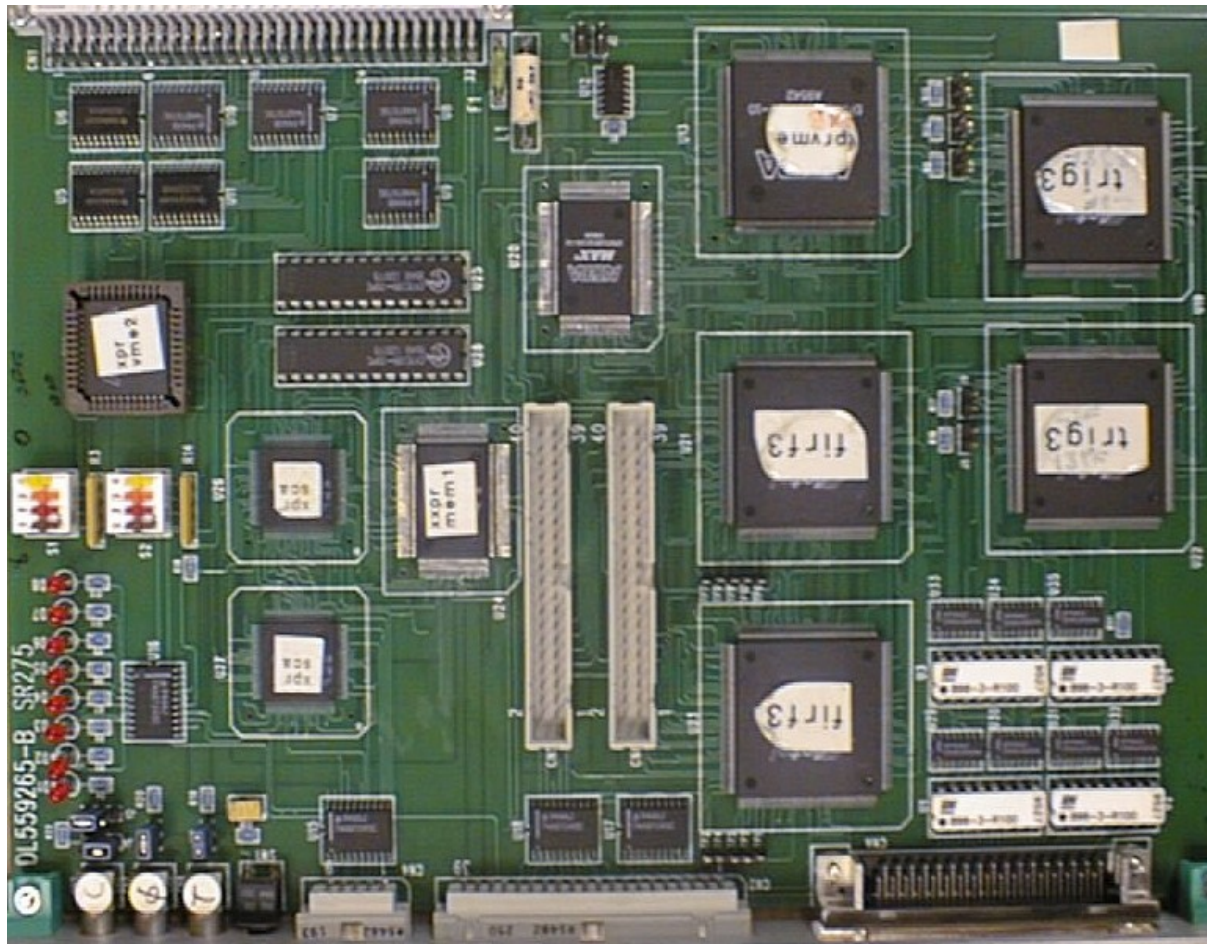
Note the **flexibility** statement



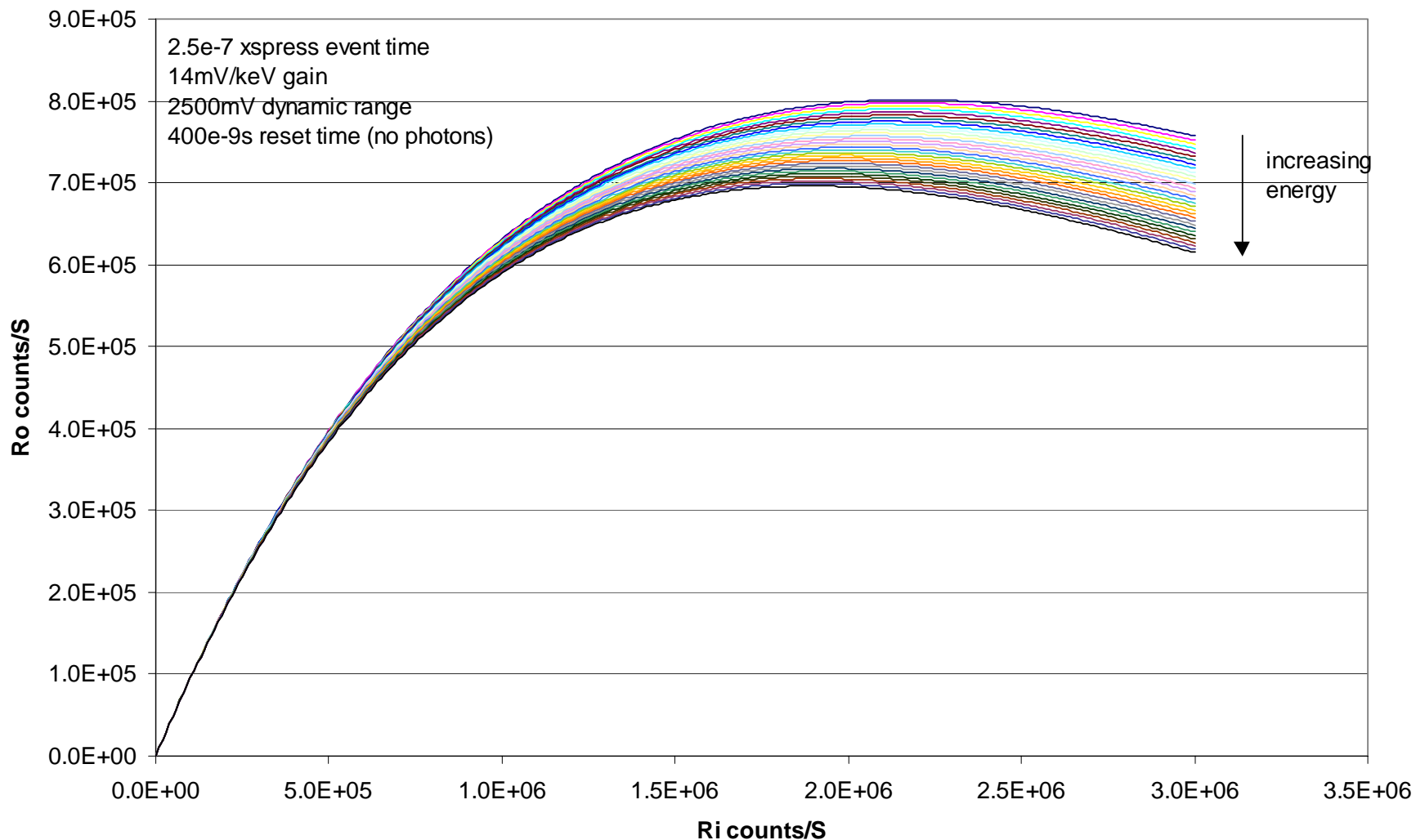
X-SPRESS DATA FLOW



X-SPRESS VME DIGITAL PROCESSOR (CUSTOM BUILT)

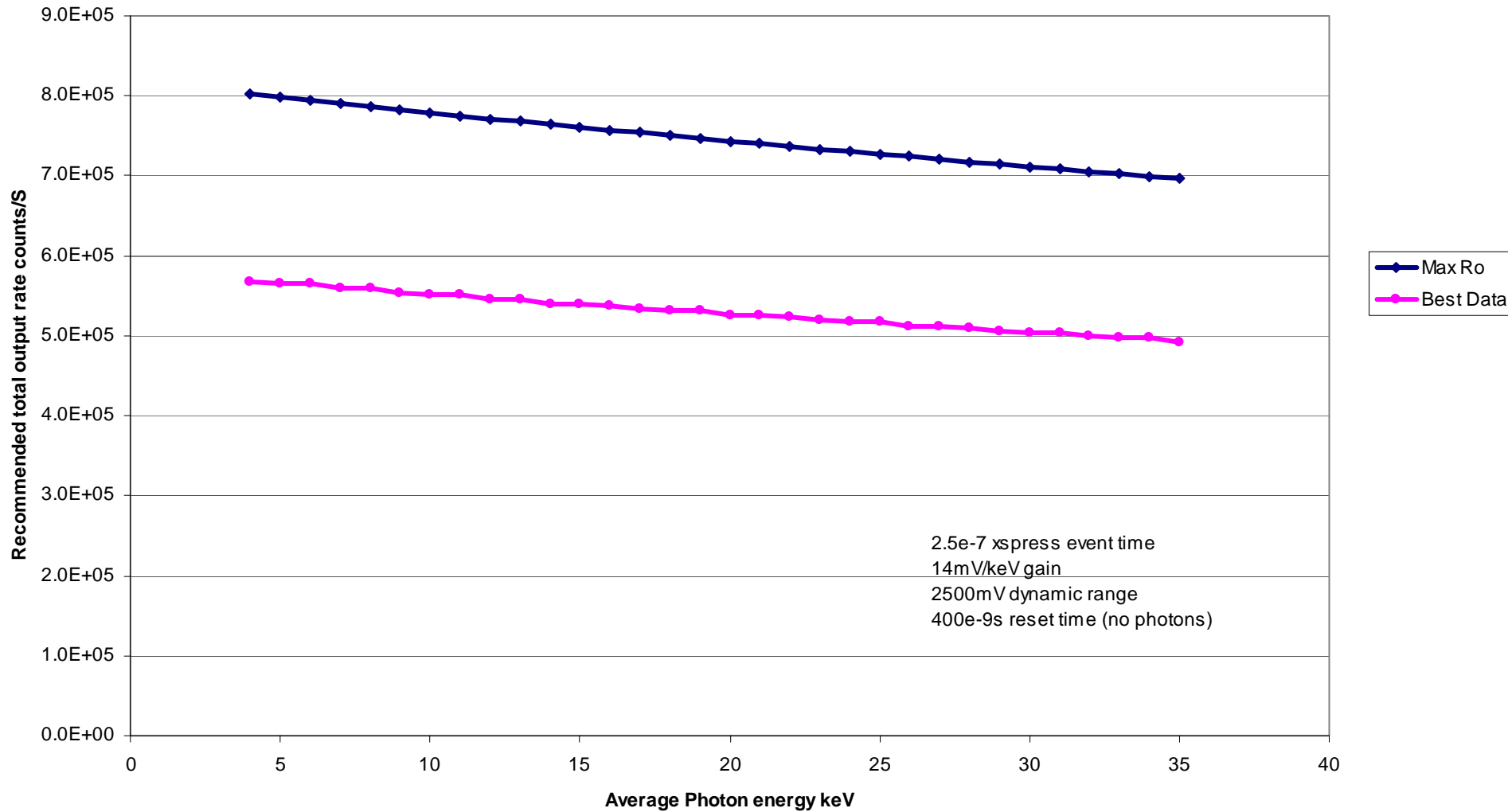


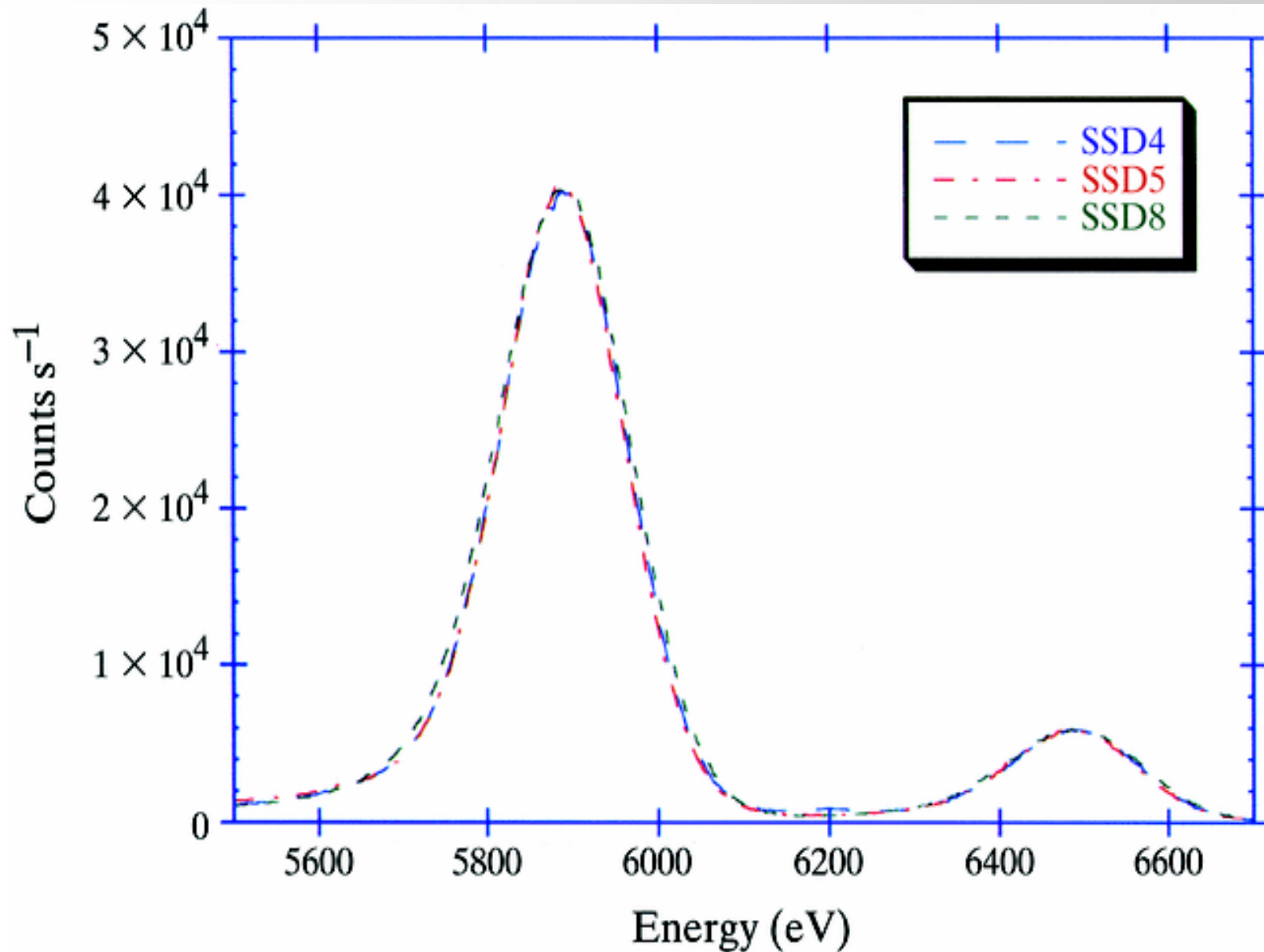
CTRAIN(IGS-09#02)/XSPRESS Ro Vs Ri for Xray enegries 5 to 35keV

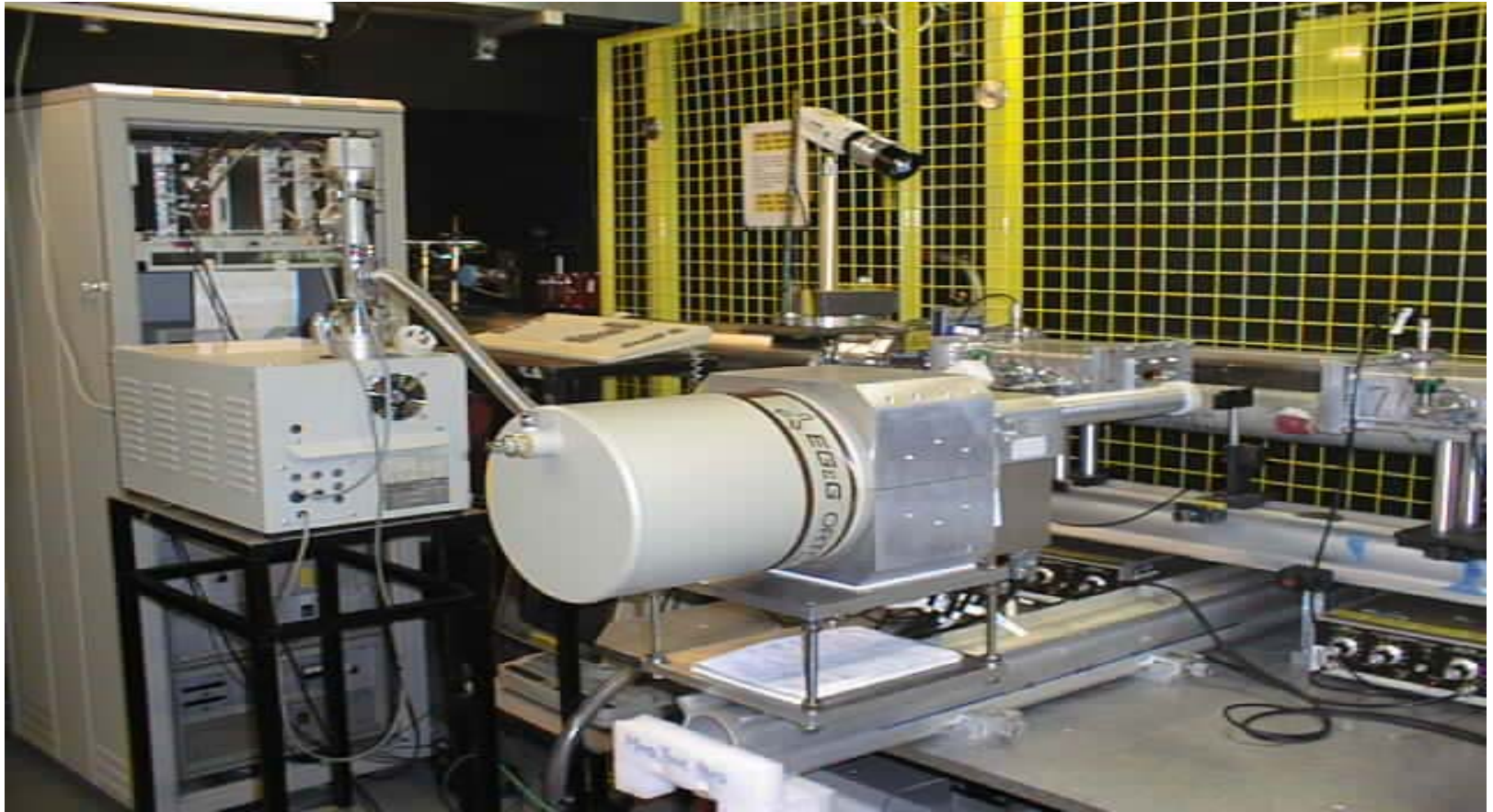


C-TRAIN XSPRESS RATES

Recomended maximum XSPRESS output rate vs spectral energy







XSPRESS is an adaptive system.

It takes as much time as available to obtain information on X-ray pulses.

That information is stored.

So we can change the effective resolution of the detector system on the fly.

Only select very good resolution events near an edge and correct for pile-up and then open up the throughput as the resolution requirements relax above the edge but more photons help statistics.

Because as soon as C-TRAIN X-SPRESS was ready it was on beamline taking data.

This is good as it proves that it was needed

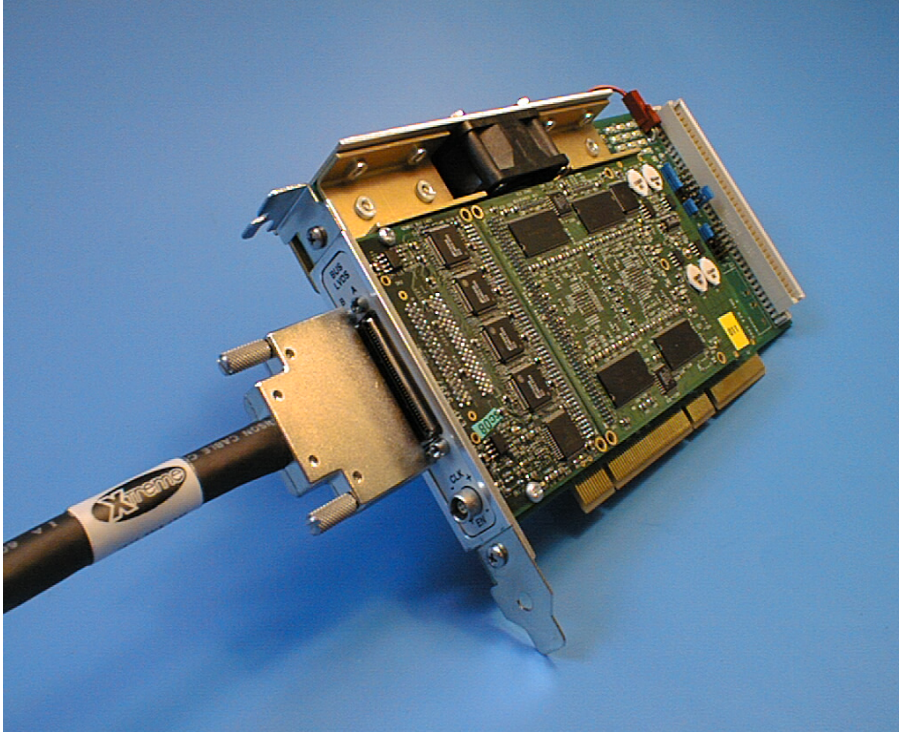
But bad for realising the full potential

and increases the development time still further.(difficult to get back)

Locks you in to incremental development.

Some people like this!

- **4 element C-TRAIN FOR LINE 10 Protein Crystallography Station on SRS**
- **After that C-TRAIN on DIAMOND?**
- **DAQ:-**
- **New Spectral Storage technique to be tested on 16.5 and 7.1 at the SRS.**
- **X-SPRESS will move to Generic DAQ implementation X-SPRESS2**
- **This will be a future proofed implementation which will be able to make best use of electronics development as it occurs.**



- **Currently 18 in service**
 - **New batch 10 - 15 modules**
Particle Physics
 - **New Virtex II Digital Front End**
 - **New Developments**
 - 14 bit ADC Front End
 - Start with existing 12 bit ADC Front End
- Estimate 4 channels per board of X-SPRESS
in GDAQ

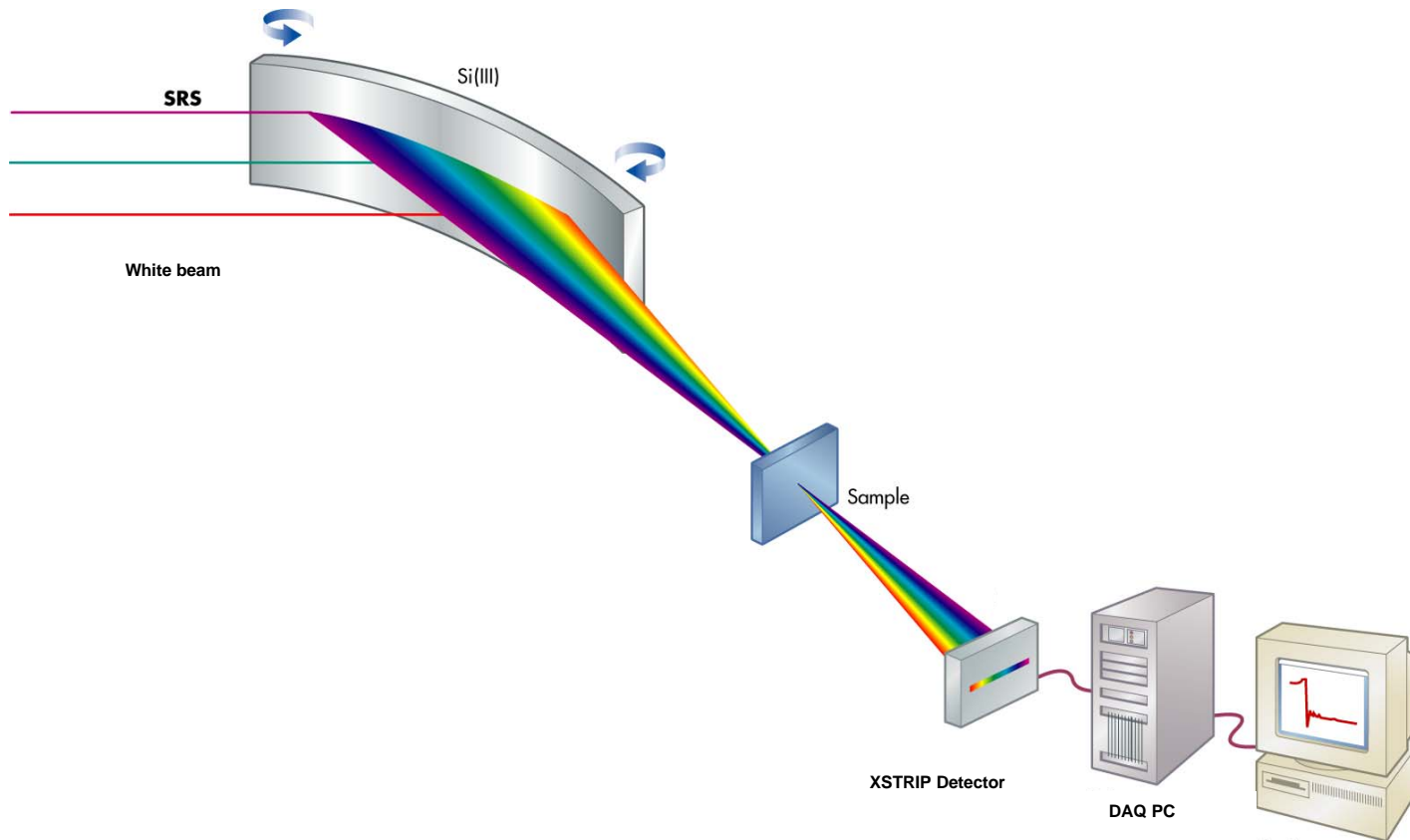
C-Train XSPRESS shows how you can get there.

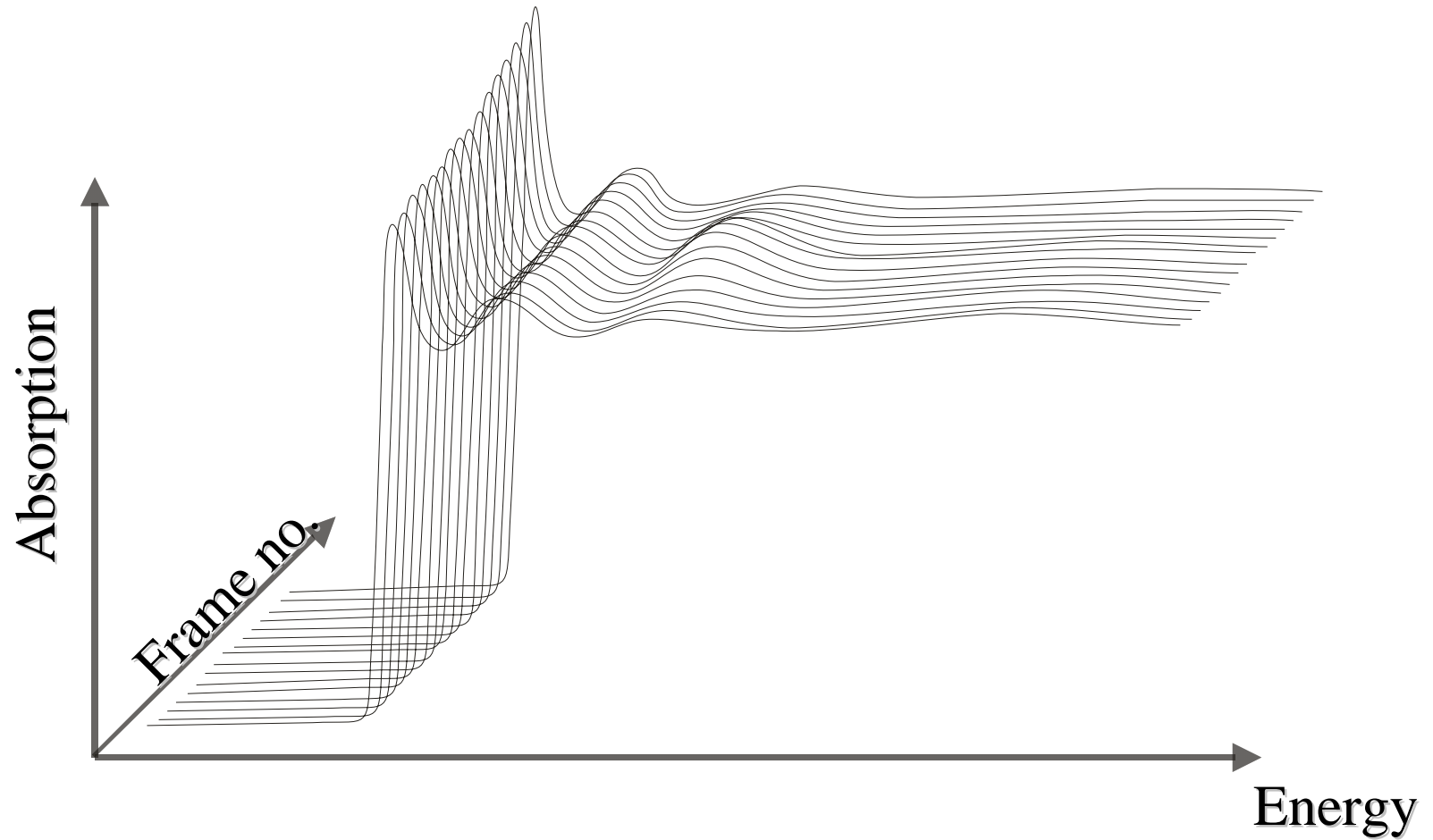
But is there another way?

The XSTRIP project was completed in approx:-18 months.

The project was started in May 1999 and taking data in January 2001.

Prototyping had been completed in an 12 month period prior to this borrowing technology and staff from HEP.

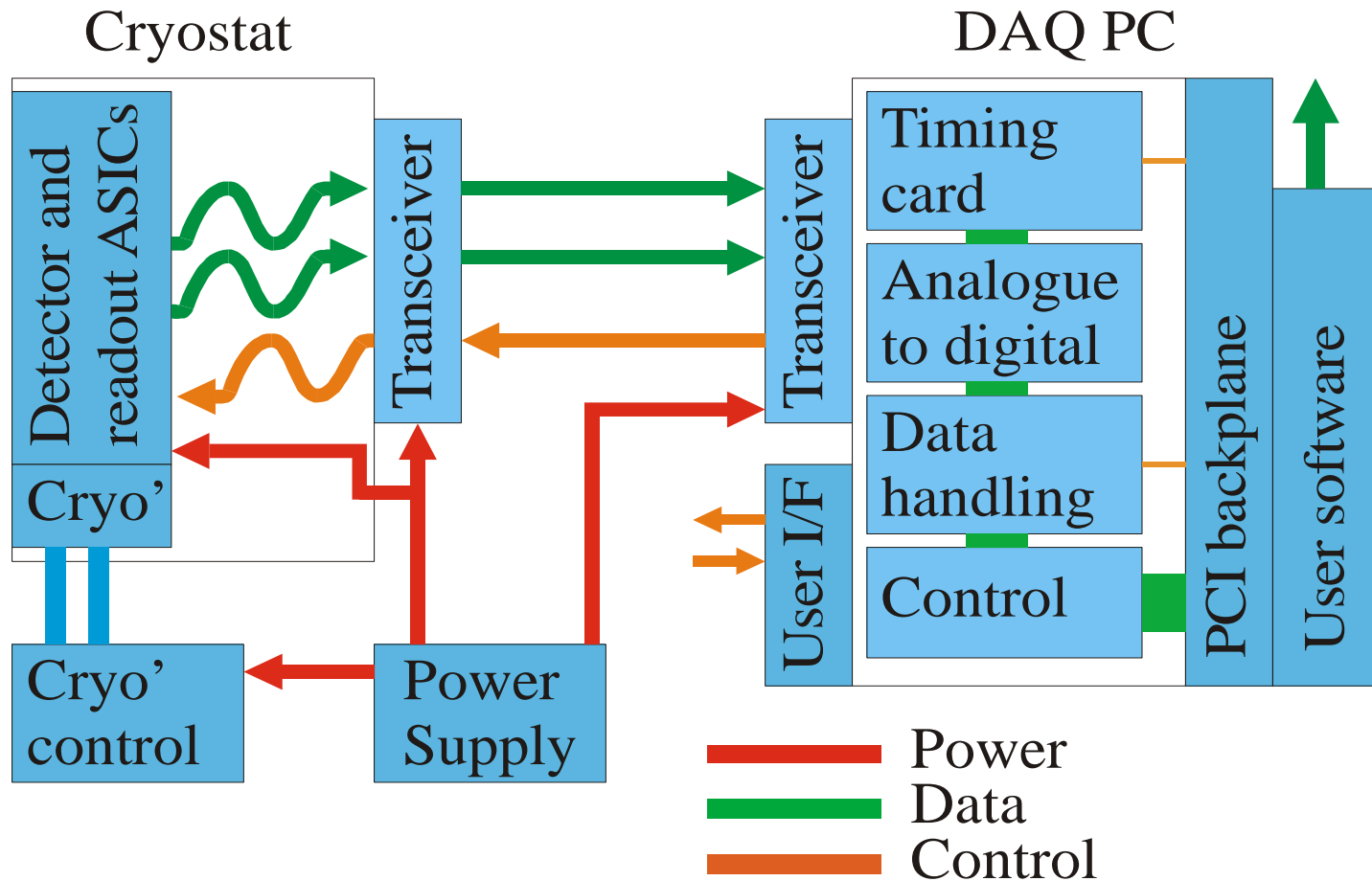


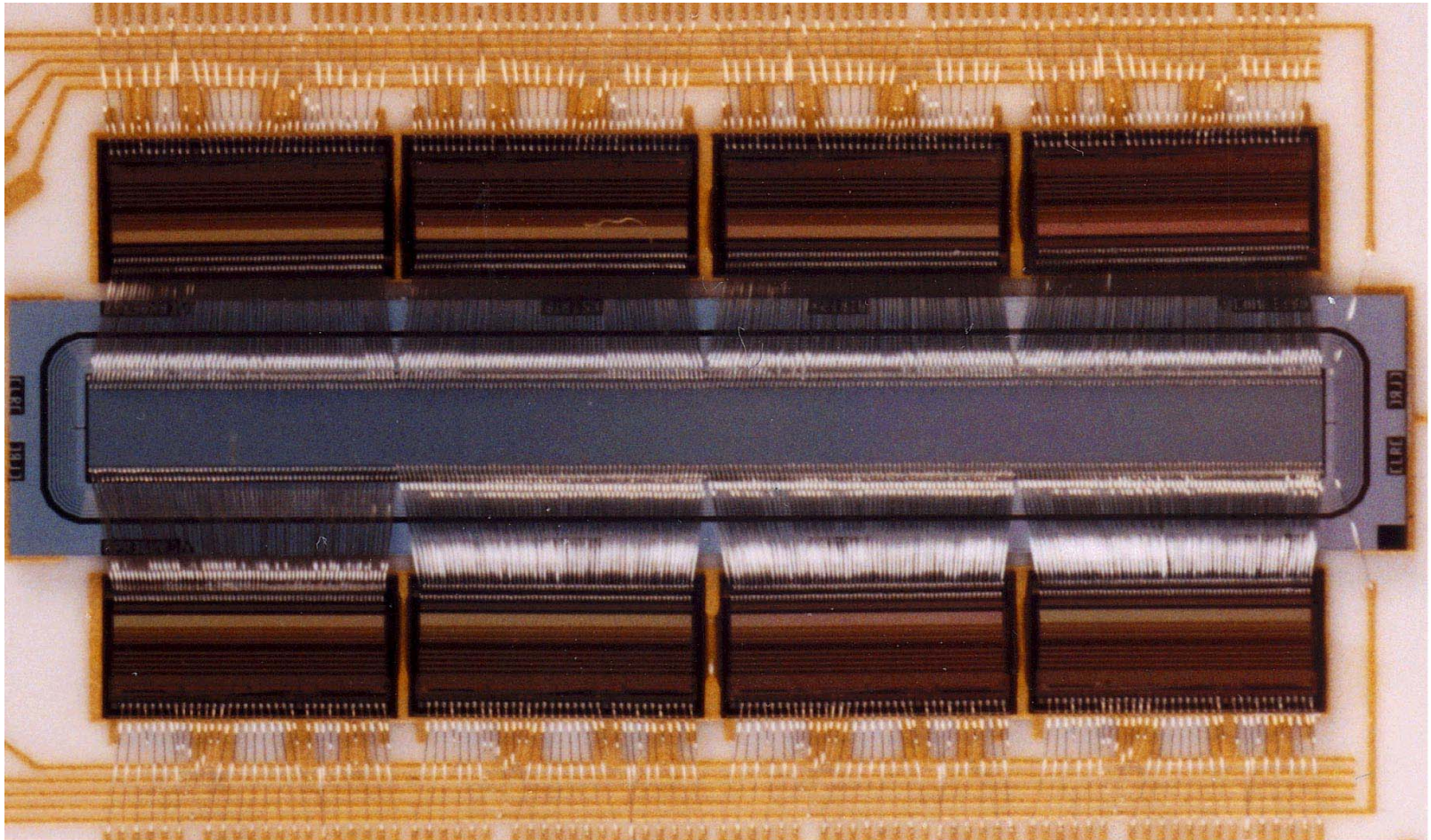


- In EXAFS ‘quick’ means a minute or less.
- Most chemical reactions \ll minute
- Energy Dispersive EXAFS (EDE).
- Currently commercial PDAs or CCDs.
- But for these the vast majority of chemical reactions lie beyond their capability.

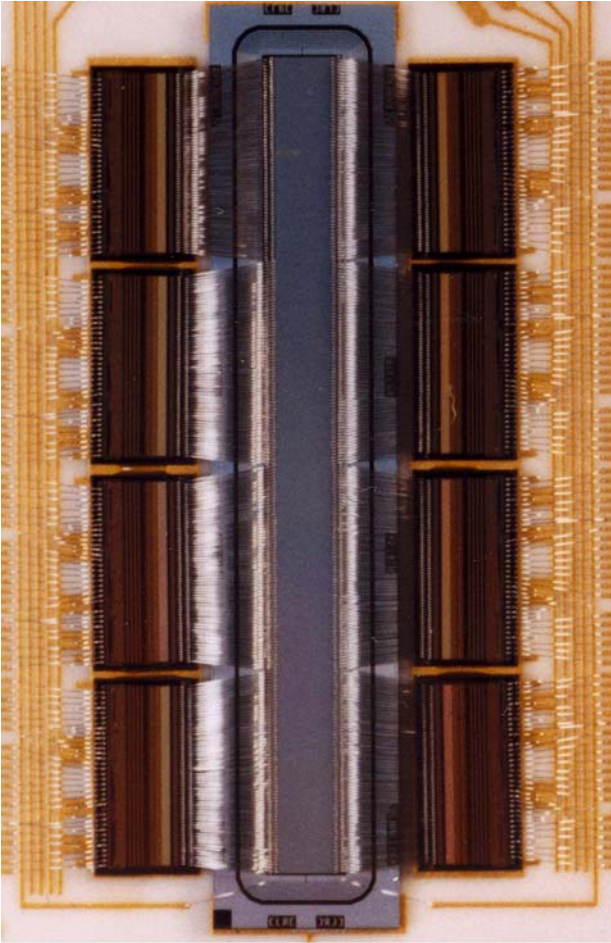
- **Custom designed detector system for Energy Dispersed EXAFS**
- **Detector : 1024 pixel Si mstrip (25 micron pitch)**
- **XCHIP : Front end readout ASIC**
- **DAQ system: PC based**

XSTRIP Block Diagram





Detector Head

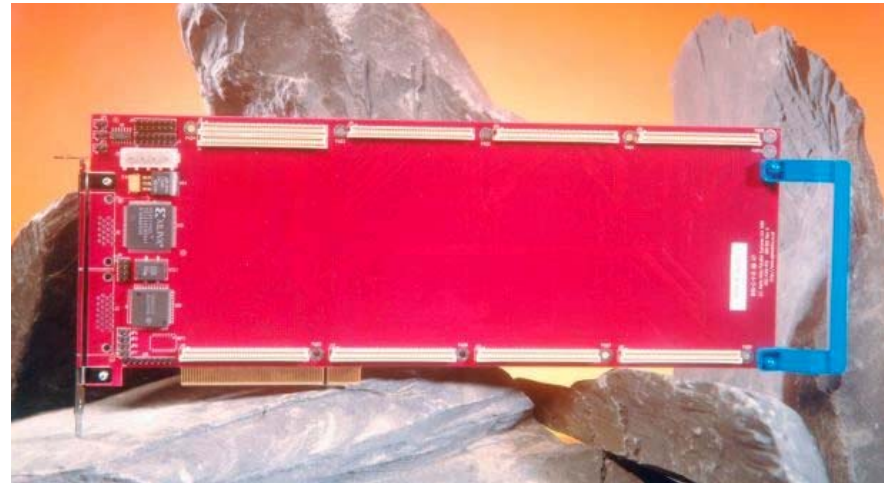


- 25mm long, 500 μ m thick Si detector, 1024, 25 micron by 2.5mm diodes.
- 8 XCHIPs , 0.5 micron C-MOS, 128 channels of charge integrating preamp, 4 readout nodes per chip
- Ceramic MCM with good thermal properties
- DAQ 32 channels of 14 bit ADCs

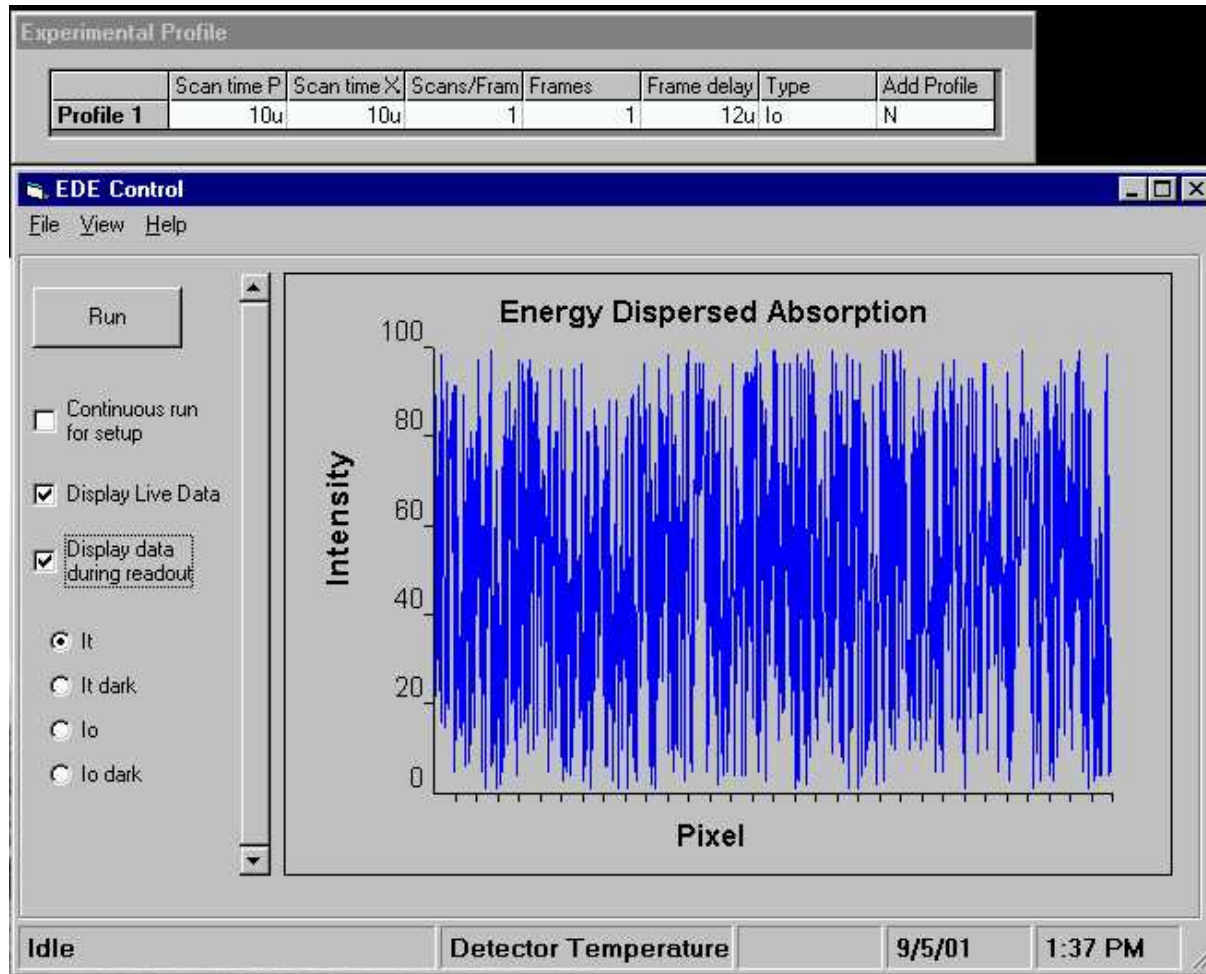


- **Turnkey solution from Sundance.**
- **2 PCI carrier boards handling a total 320MB data per second.**
- **PCI carriers comprise 4 slots.**
 - 2 x 8 channel 14bit, 5MSPS ADCs.
 - 1 x VIRTEX FPGA with 8 MB memory.
 - 1 x DSP (Texas Instruments C6x family).

XSTRIP SUNDANCE DAQ



Courtesy
Sundance



- Profiles
- TCP/IP interface
- Interface to station macros

Parameter	Specification	1.1.1 Actual	On target
Maximum photons	$> 2.5 \times 10^9$ photons / pixel	4.5×10^9 (@15keV)	✓
Integration time	10 μ s minimum	1 μ s minimum	✓
Linearity	$< 0.2\%$	0.04%	✓
Readout Efficiency	$> 75\%$	90% at 10 μ s	✓
Efficiency	$> 50\%$ for the whole system	60%	✓
Dark Current	$< 10\%$ over maximum integration period	0.5%	✓
Radiation Resistance	Not specified	Some non-fatal damage observed	✓
Energy Range	5-25 keV	Tested 7-15 keV	✓

A1 (lower) and A2 (upper) voltages.

8-Jan-01

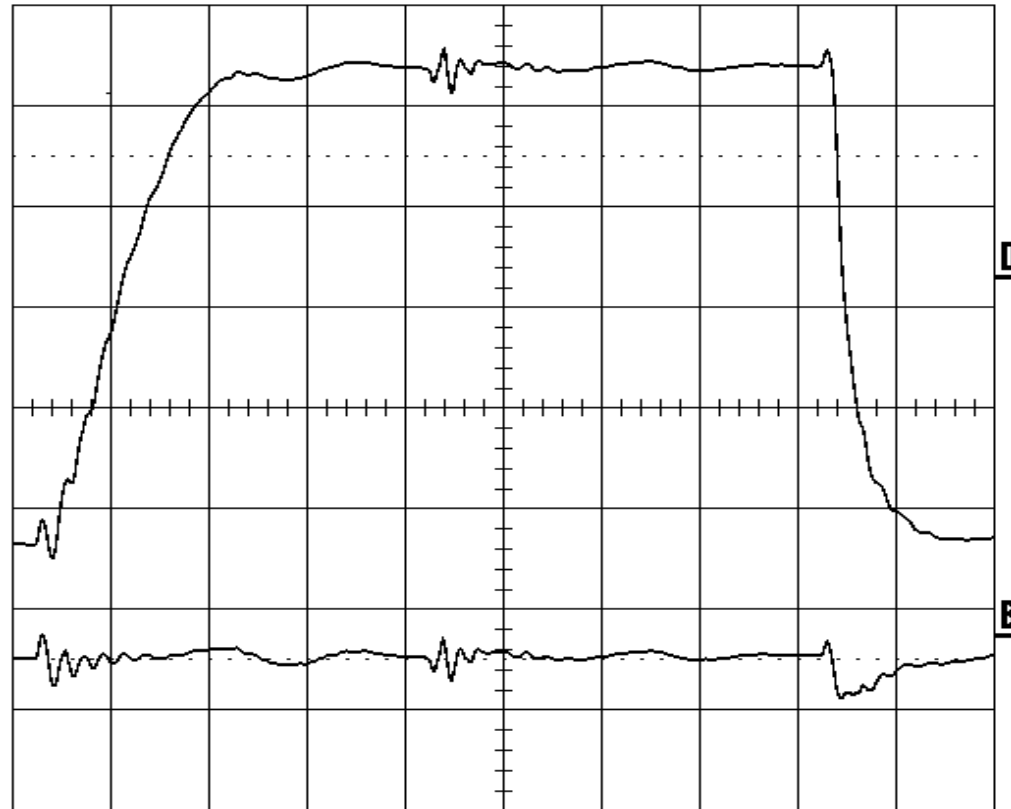
14:00:53

B: Average (2)
50 ns
200 mV
53 swps

D: M4
50 ns
200 mV
53 swps

50 ns RIS

1	.2	V	AC	
2	20	mV	AC	$\times 10$
3	20	mV	DC	$\times 10$
4	1	V	DC	



XSTRIP OUTPUT Differential

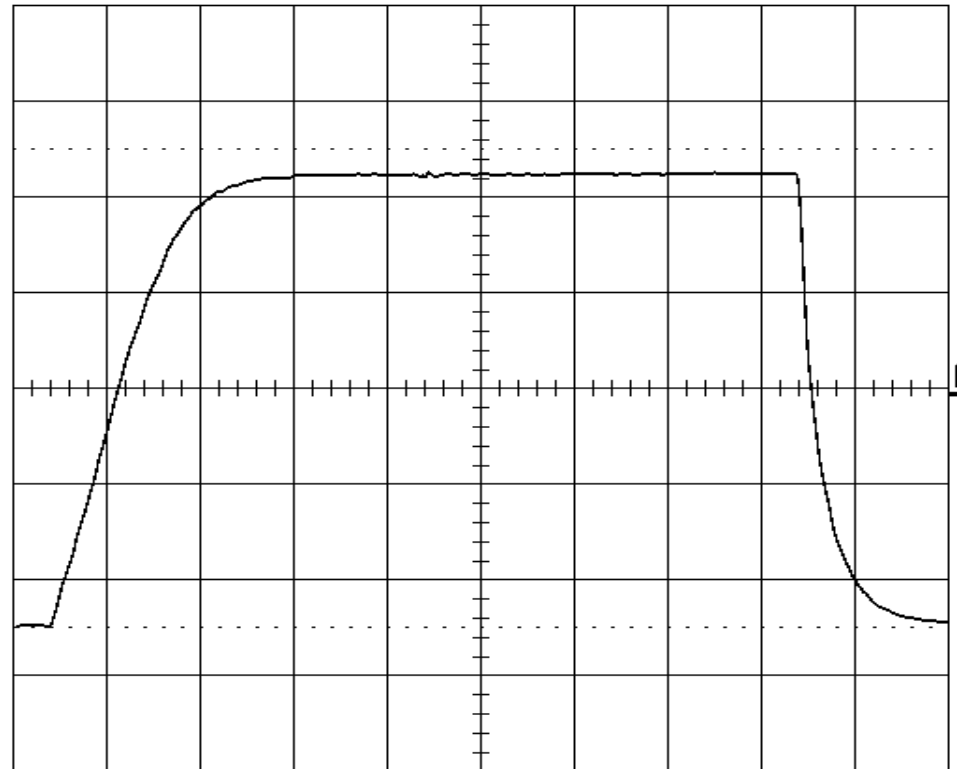
A1-A2 voltage : rise time ~150ns, fall-time ~80ns (to ~0.1% accuracy)

8-Jan-01
14:09:02

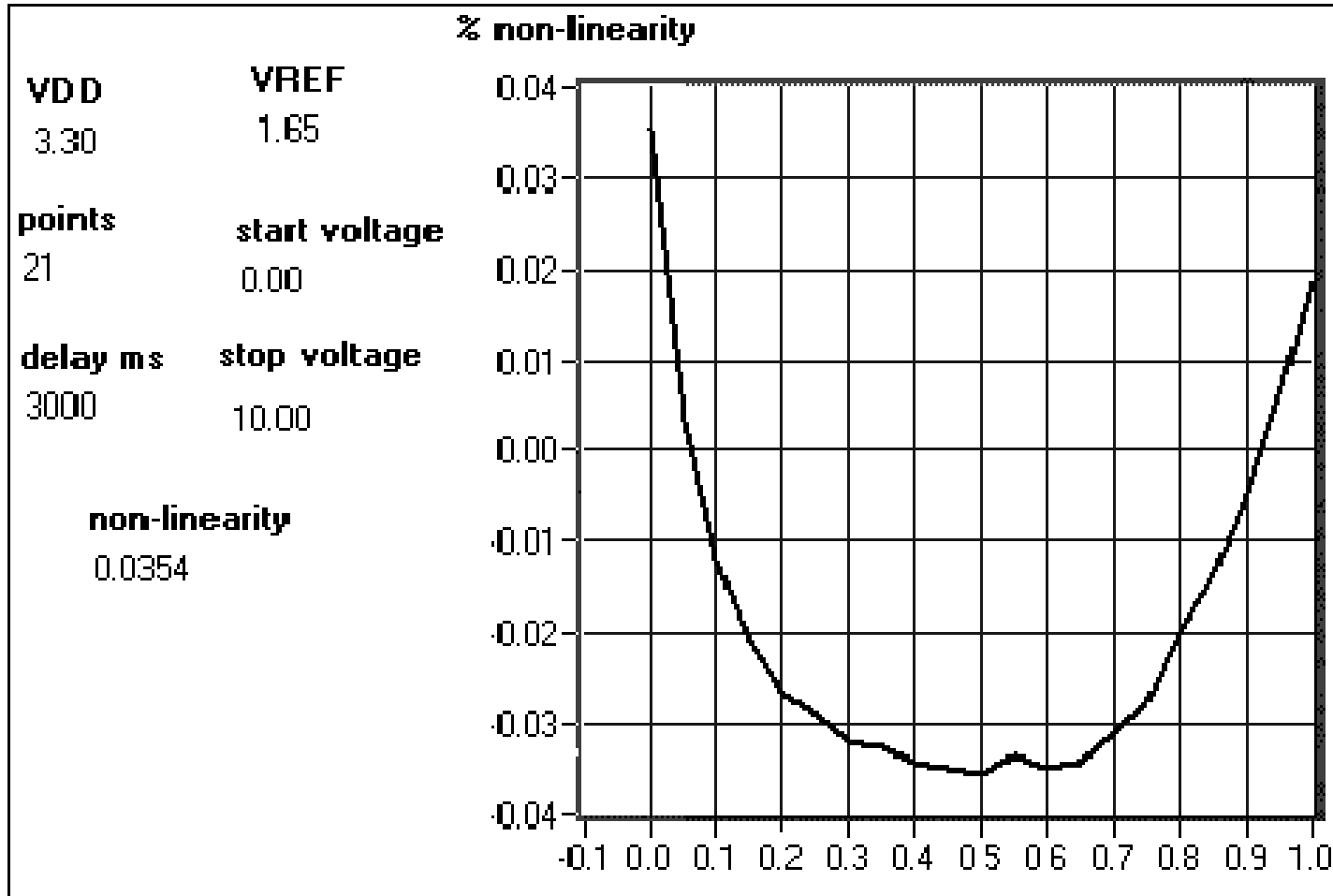
A: D-B
50 ns
200 mV
53 swps

50 ns RIS

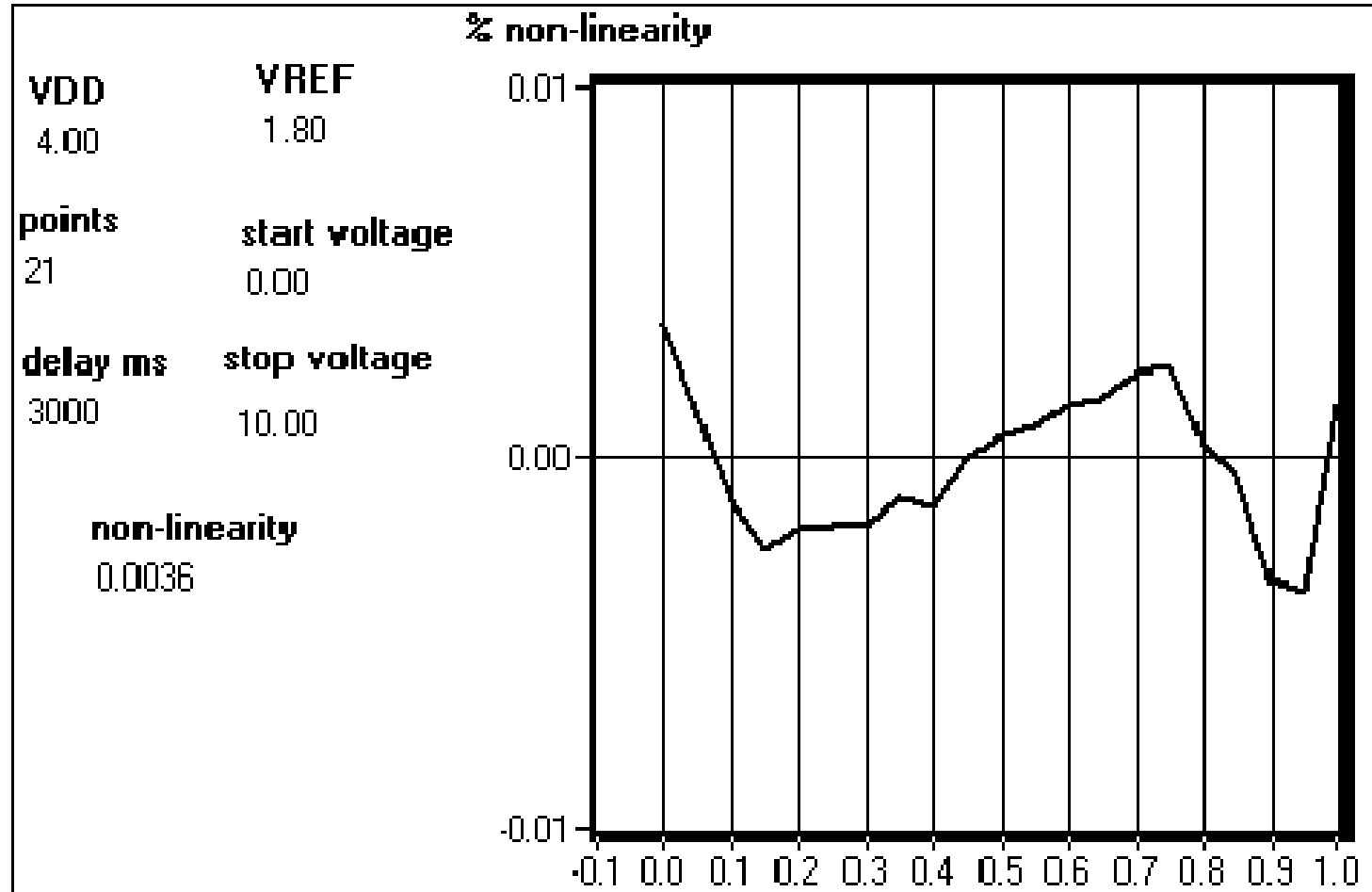
1	.2	V	AC	
2	20	mV	AC	$\times 10$
3	20	mV	DC	$\times 10$
4	1	V	DC	



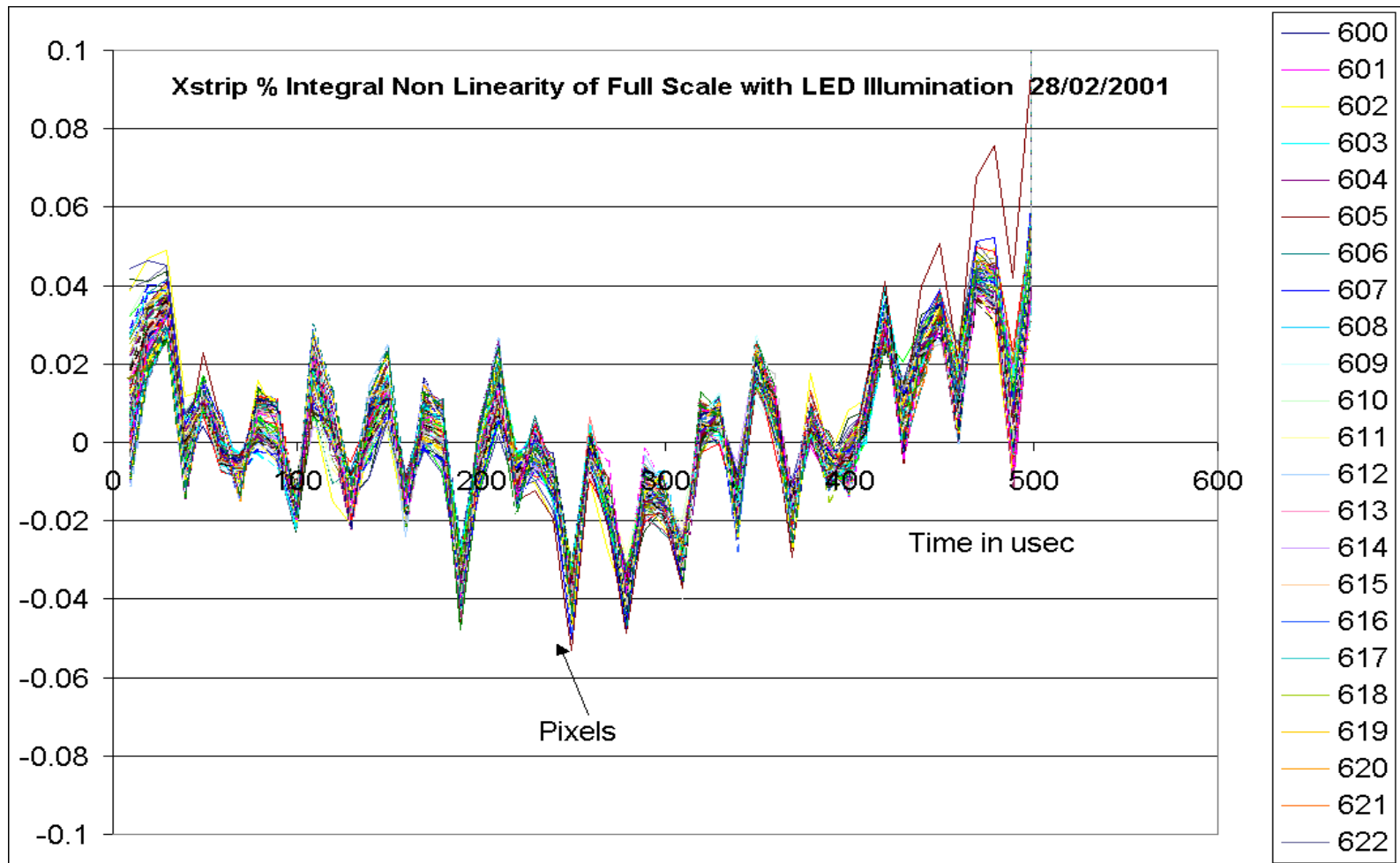
Optimisation with operating voltage



Optimisation with operating Voltage



Testing with detector



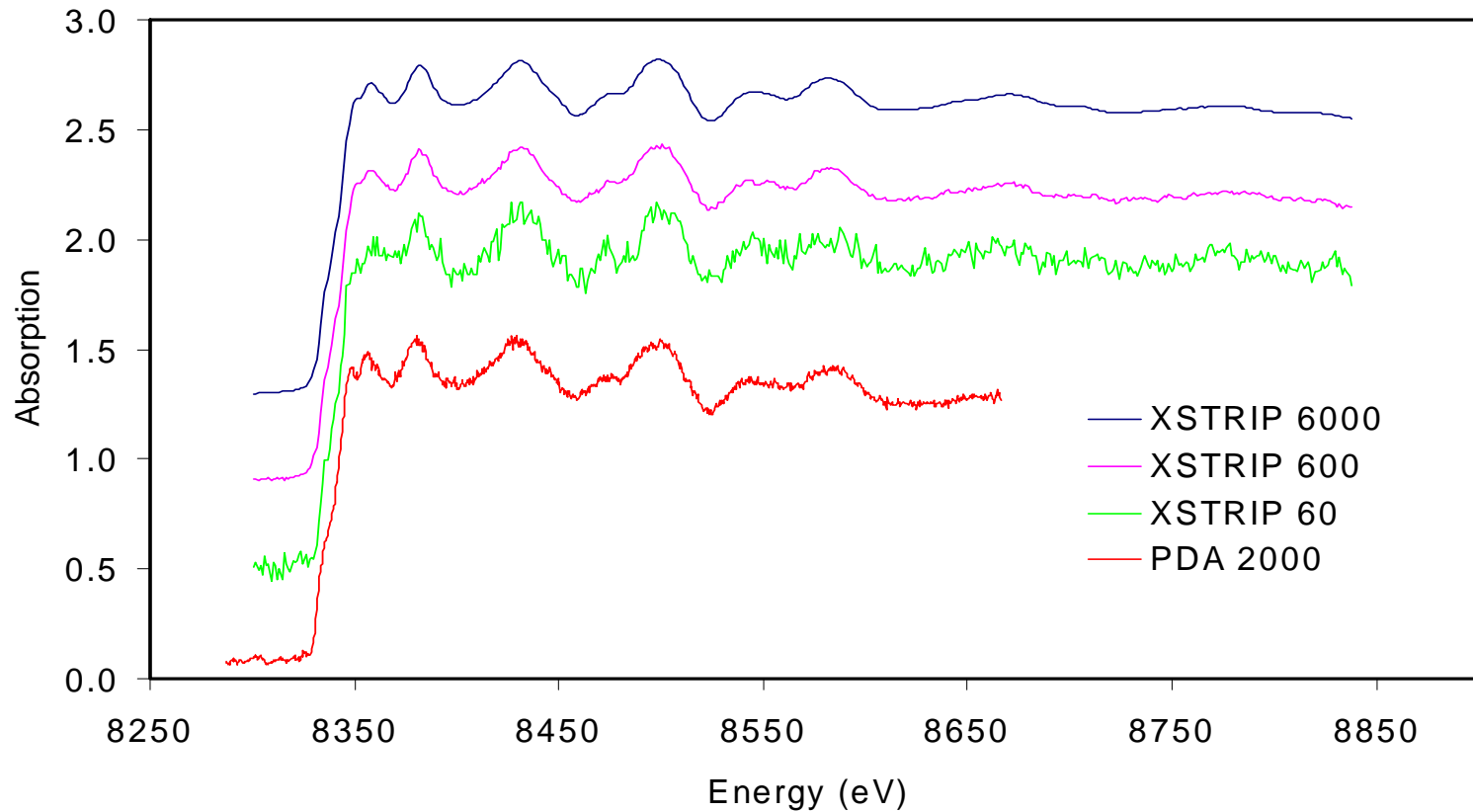


Figure 3a: 5 µm Ni foil

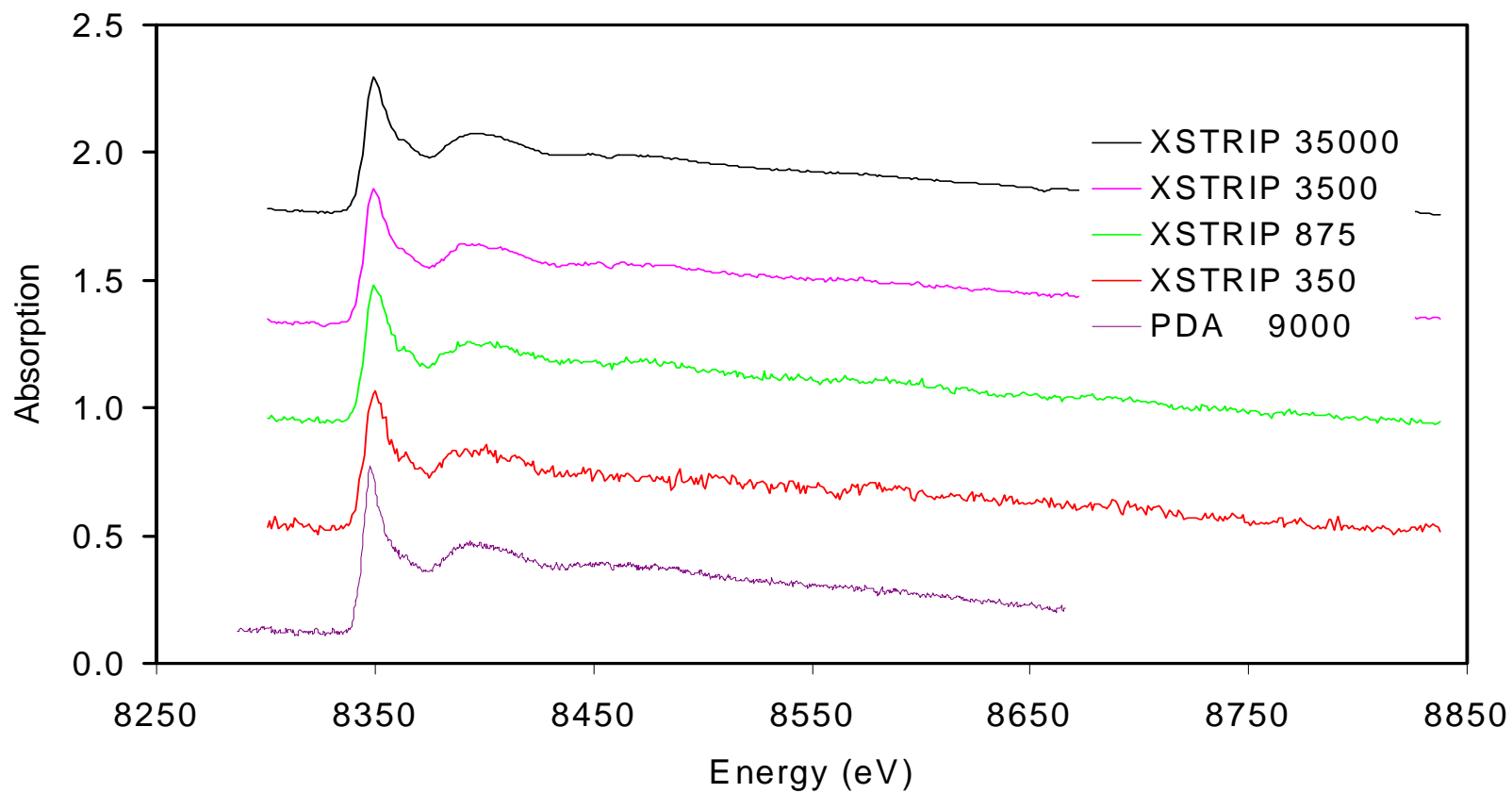
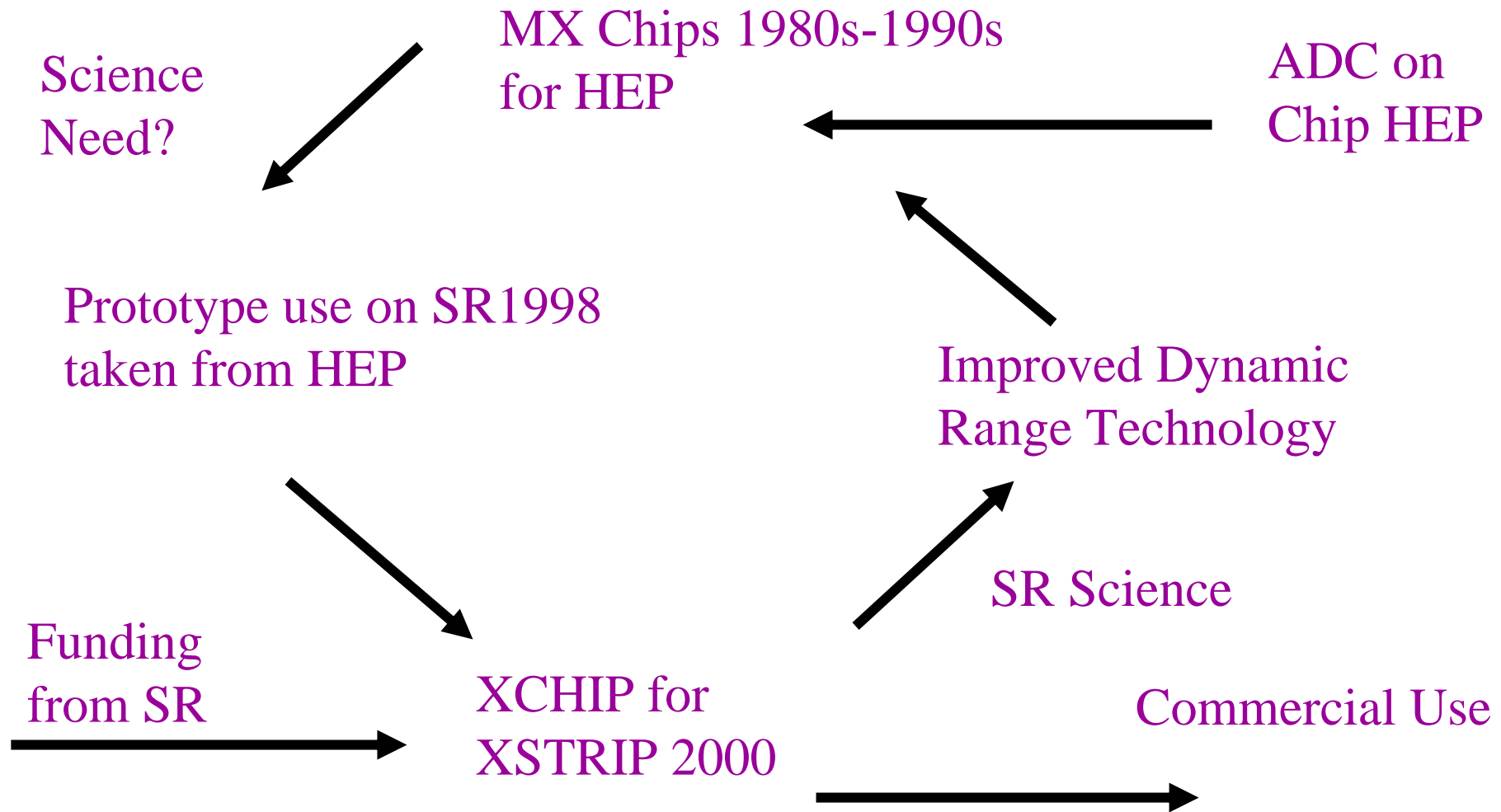


Fig 3b 100 mM NiCl_2 solution



Incremental developments are OK but not radical enough to close the gaps.

(you do the best that you can with what you have)

C-TRAIN X-SPRESS born out of this.

Building in re-use and feedback to the place where the technology came from is a good idea.

XSTRIP is fast but not fast enough for science.

However it is fast enough to study beam instabilities

If you want data on the millisecond to microsecond timescale you need a beam stable to that. (or a reliable way of measuring and correcting it)

The future breaks into two areas:-

NEAR-TERM

Things that we can do and only need funding to achieve.

development- mostly engineering

FURTHER AWAY

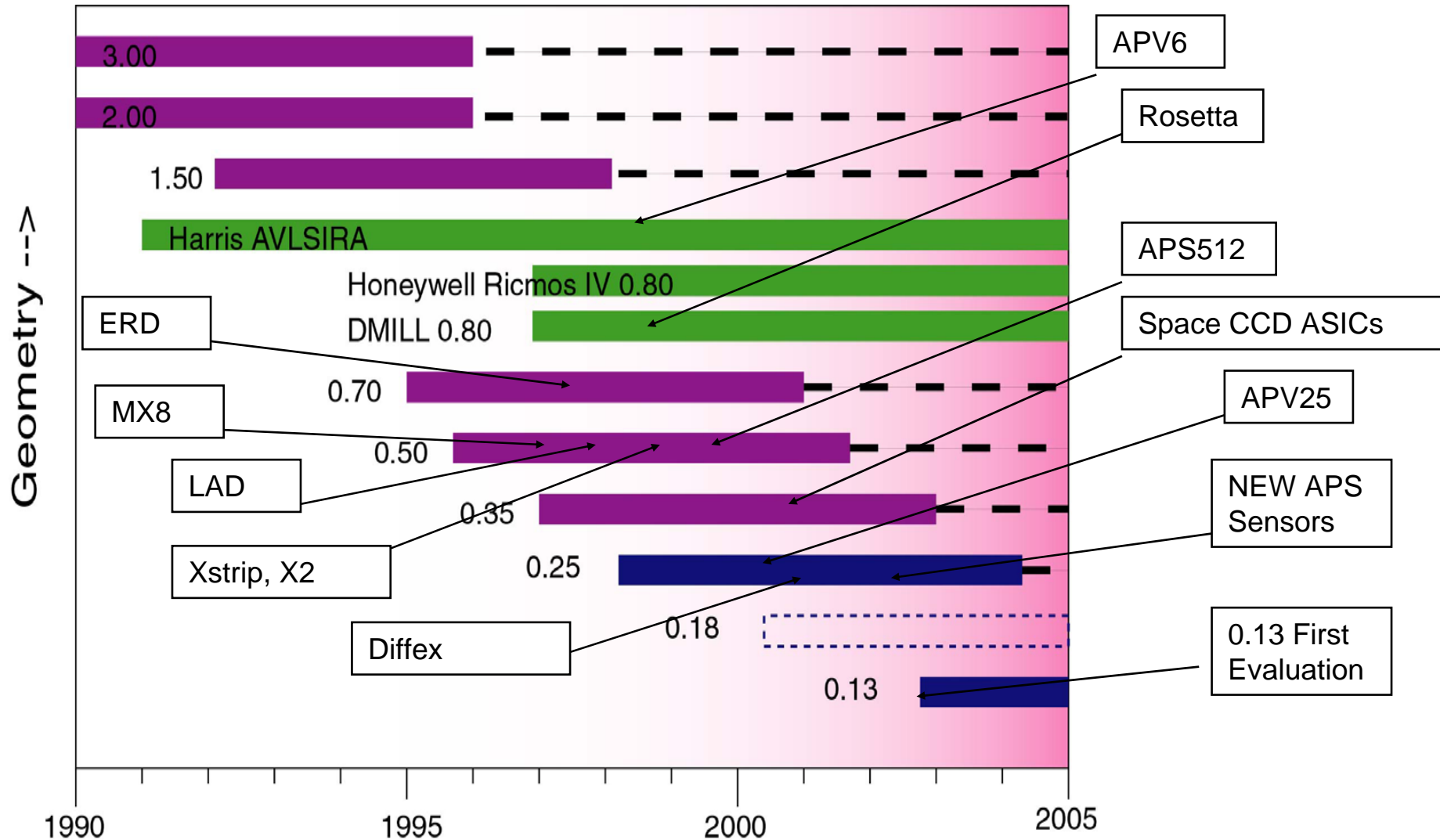
things that we don't know how to do

research-a mixture of science, engineering and time

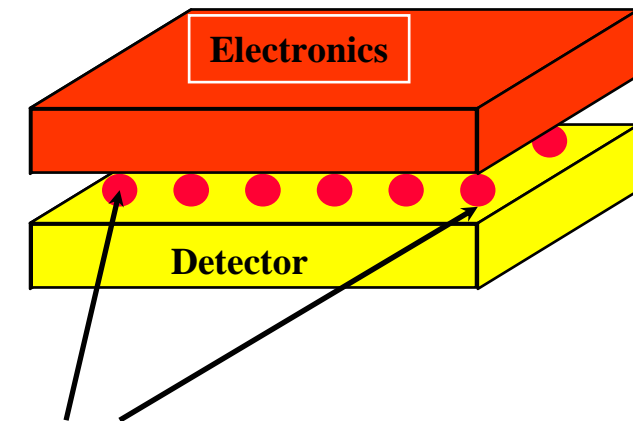
Both near and long term futures rely on microelectronics and probably involve pixellated detectors of one form or another.

The days of CCDs and phosphor screens are numbered.

Current and future near term Si strip and pixel detectors rely on microelectronics

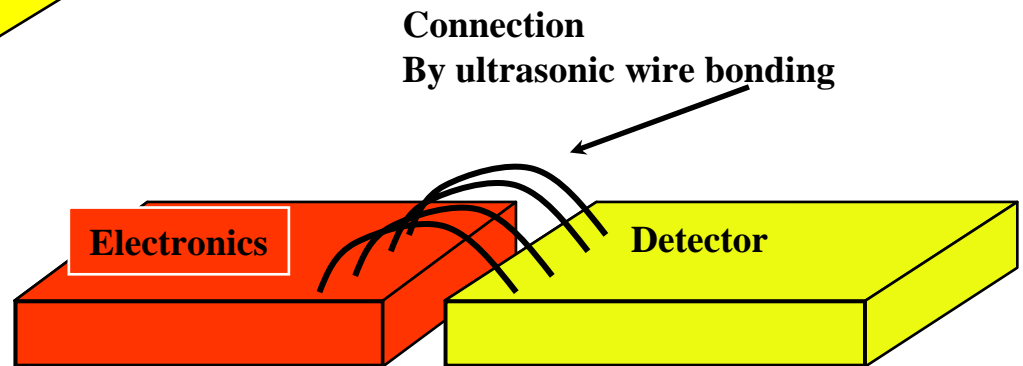


Pixel



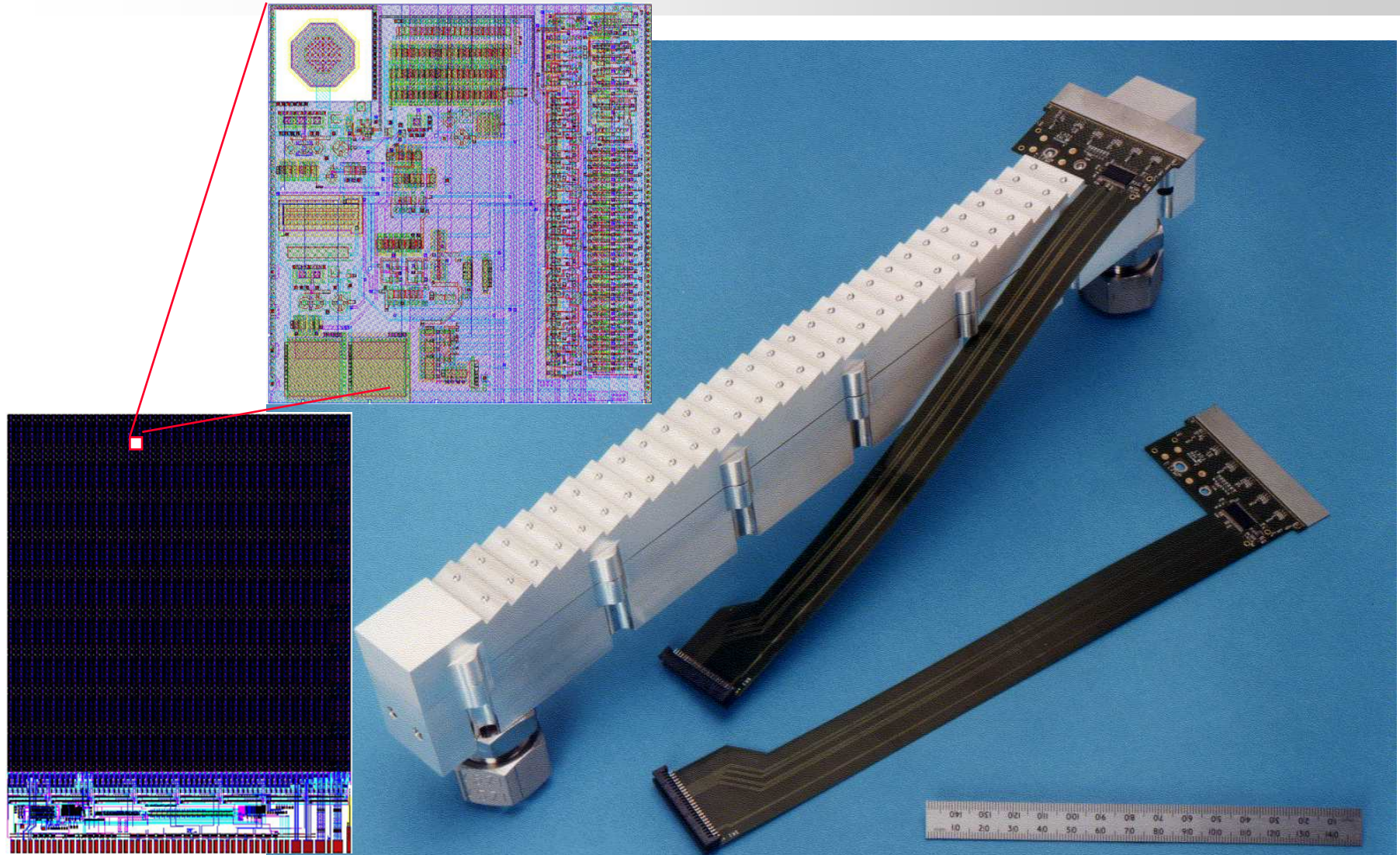
Connection
By bump bonding

Linear



Connection
By ultrasonic wire bonding

SR Detector Development Si Pixels



Photon counting ($4 \cdot 10^9/\text{pix}$),
 2d(150 μm) 4-25keV,
 1MHz/pixel

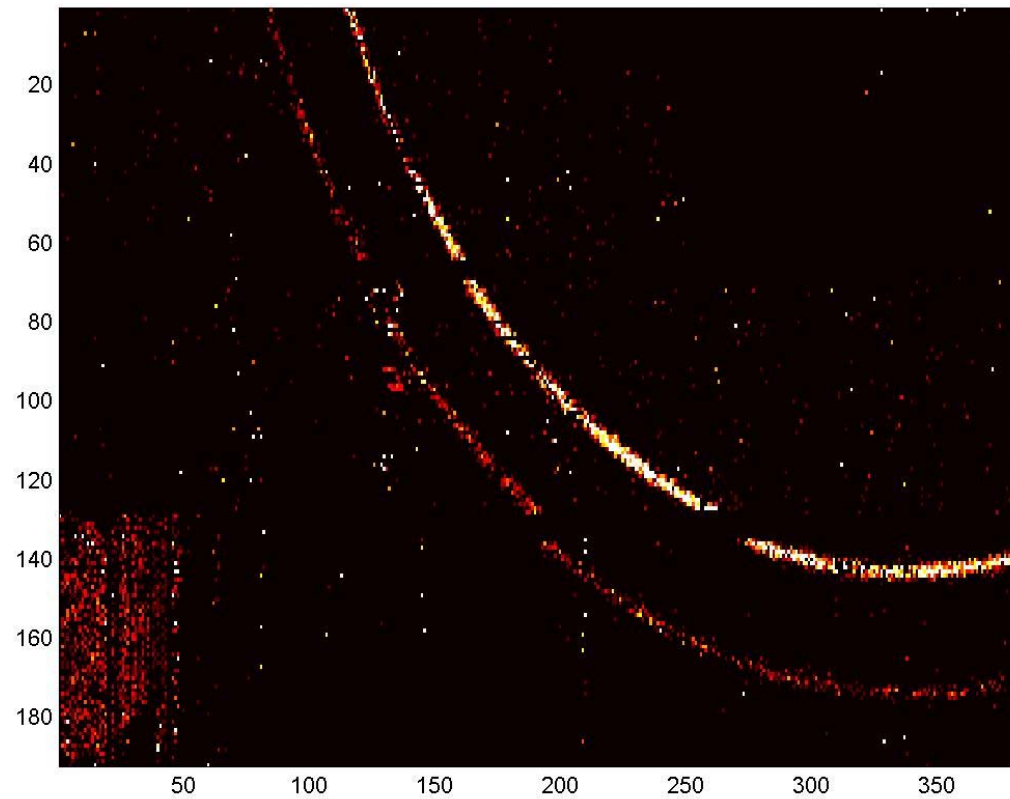
Bump Bonding

Not stable for small numbers.

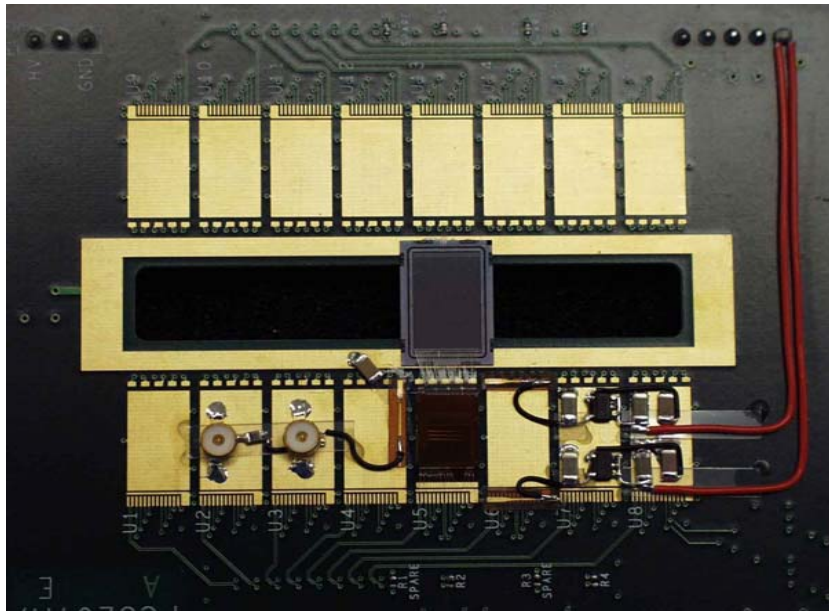
It can be done and has been done (mobile phones and Computers)

But if critical to both HEP and SR then we need to set-up a facility which can be dedicated to our needs.

This issue is near-term and has been near-term since the early 1990's



Photon counting can give you energy resolution

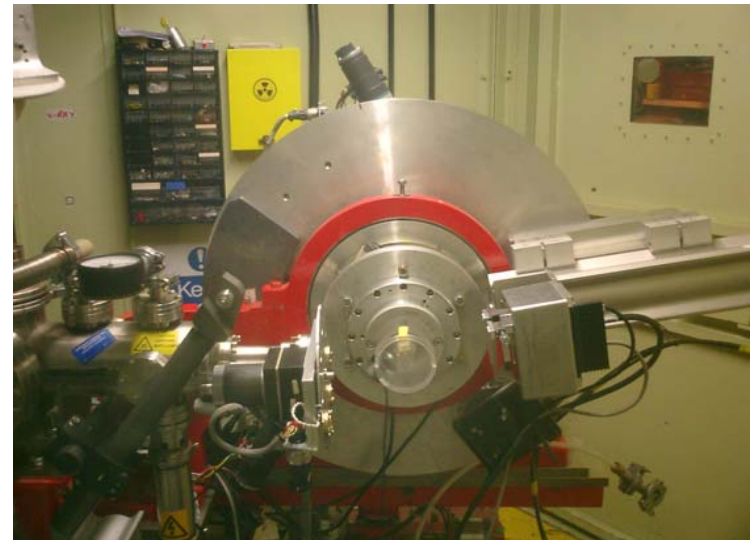


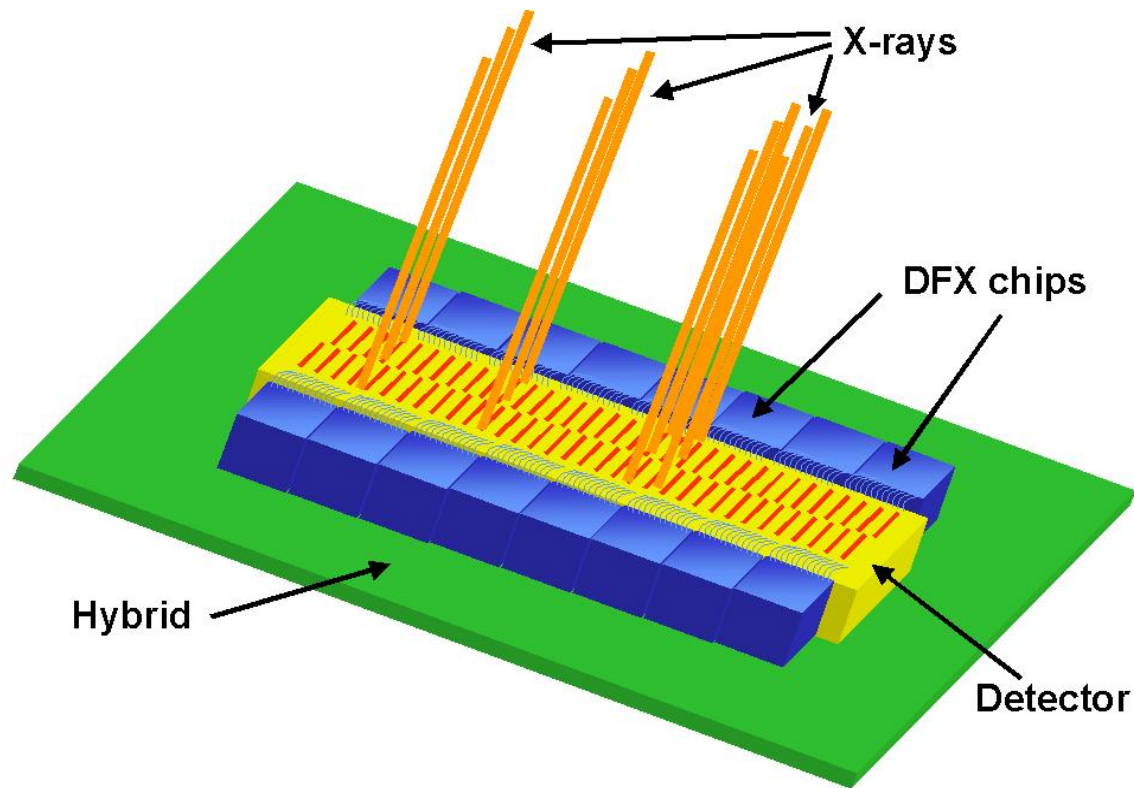
1024 channels @1MHz

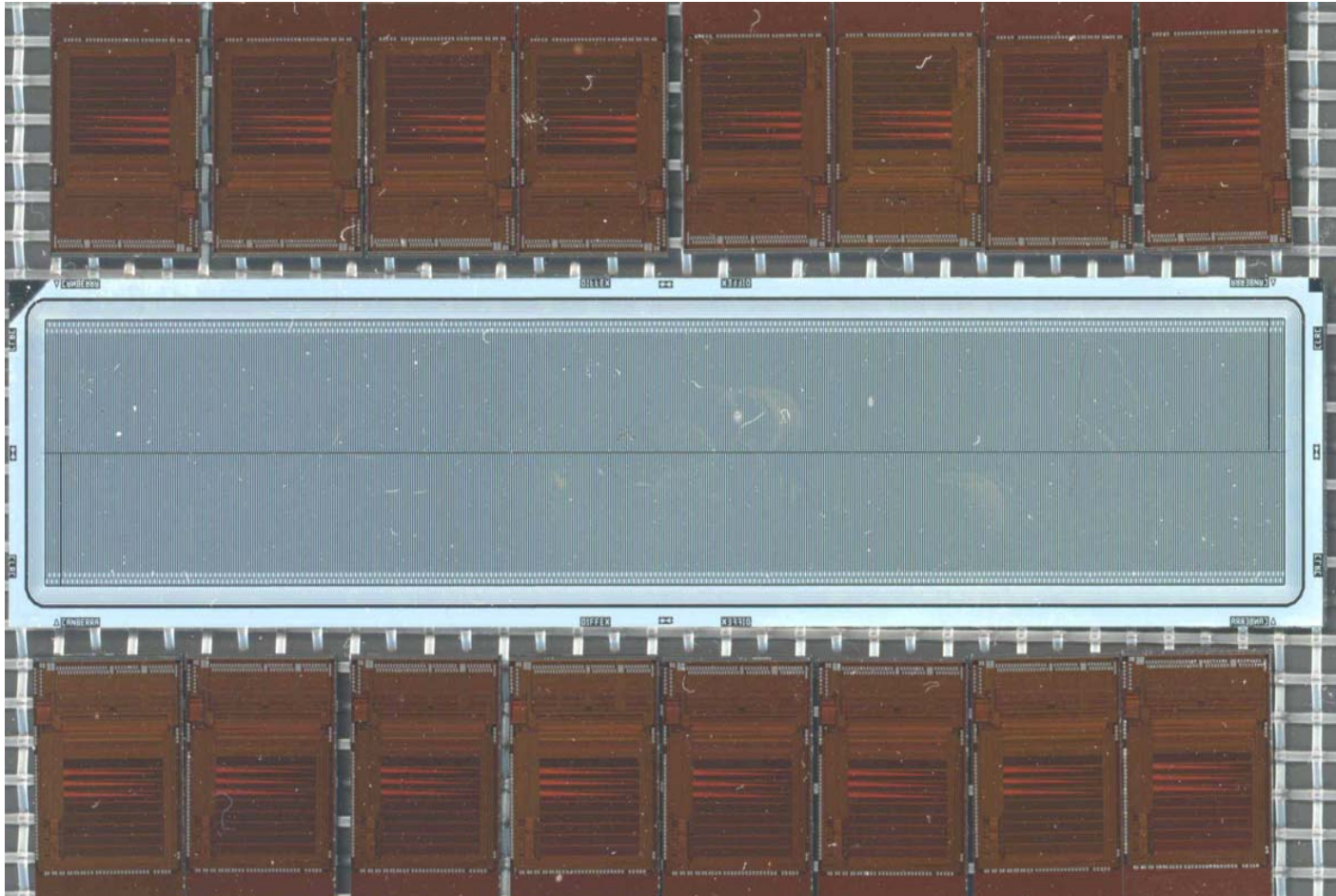
16 level disc. per strip

16 bit counters per strip

64 channels per chip







Guard Rings on planar Si introduce dead areas and are going to be difficult to remove.

Larger integration of the number of detector pixels will help. Increased size of detectors.

But where to next-

3 D silicon.

3D Si (Sherwood Parker, Ed Westbrook..)

Looks like the technology is there so it is in the realm of near-term. HEP pushing this as well.

What about other materials..

Not just 3D but higher Z planar...

GaAs, CZT. Near term or longer term?

We need to ask the astronomy and space community.

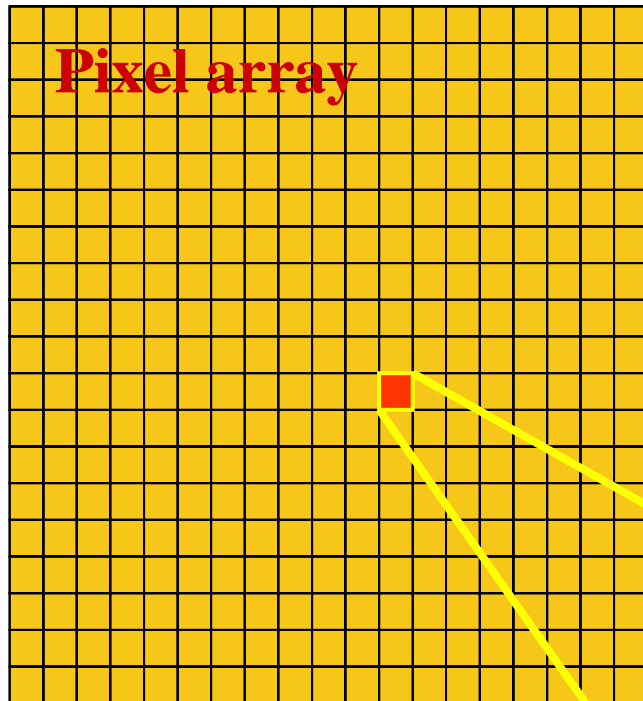
And then that opens up Superconducting detectors plus UV and IR.

Monolithic Active Pixel Sensors (MAPS) are found in web cams, mobile phones, etc.

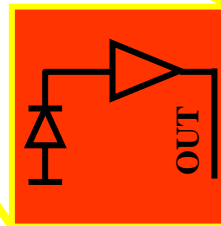
They are built in standard C-MOS processes and offer possibilities of large area detectors through stitching. (4cm by 4cm)

MAPS are pixels with active elements built in them. The active elements are user definable.

MAPS are now available in science grade.



Data processing /
conversion



Small pixels
Large pixel number (16M and
above)
Fast
Read while taking data
Low noise
High Dynamic Range
Radiation hard
Intelligence
Routine CMOS manufacture

Applications in particle physics, space, SR, neutron scattering, laser physics,
charged particle detection, confocal microscopy,...

Monolithic Active Pixels can be viewed as “CCDs with attitude”.

The possibilities with current technology are:-

very small pixels < 2 microns

non linear response (logarithmic)

pixel behaves as a counter or an integrator depending on conditions.

Just read out what is there. (self triggering)

on pixel analogue memory. (streak camera mode)

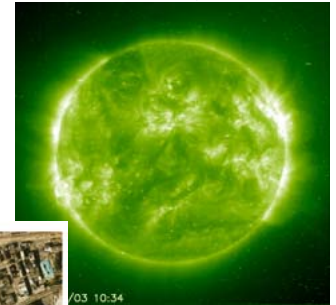
large format n_k by n_k where $n > 4$

radiation hard

The 3 sensors are prototypes in a 0.25 μm technology, optimised for image sensors for different applications :

Area sensor for ESA's Solar Orbiter for EUV

imaging of Sun: 4K*3K sensor, 5 μm pixel,
linearity over 14 bits



Linear sensor for Earth Observation

4K x 5 μm pixel, \rightarrow 1 m ground resolution
colour, on-chip 10-bit ADCs, \sim 1500 fps



Area sensor HEP and fast imaging ($>1\text{MHz}$):



X-ray and particle to light converters need work.

Phosphors and scintillators need better response times and better stability.

Otherwise you measure the response of the phosphor not the physical process you are trying to measure.

Better High Z detector material are needed otherwise all the photons produced are not counted.

We are not alone in needing work in this area.

For future developments there are some key factors:-

- A clear understanding of the key science drivers.
- A clear understanding of the technologies available.
- Identifying the key players who own the technologies.
- Close collaboration between Scientists and Engineers.
- Close communication through meetings such as this and other ways.
- Maybe SR can take the lead instead of HEP (bump bonding!)

There are many opportunities for detectors on SR sources to improve existing SR science by closing the gap between photon provision and detection.

In the future SR needs to use photons efficiently (FBAD!).

We must also look at what other areas have to offer.

Funding must be sufficient to do this properly in a co-ordinated way.

Let's learn from other areas of science where big international proposals are successful.

We are a global community- let's use this to our advantage!